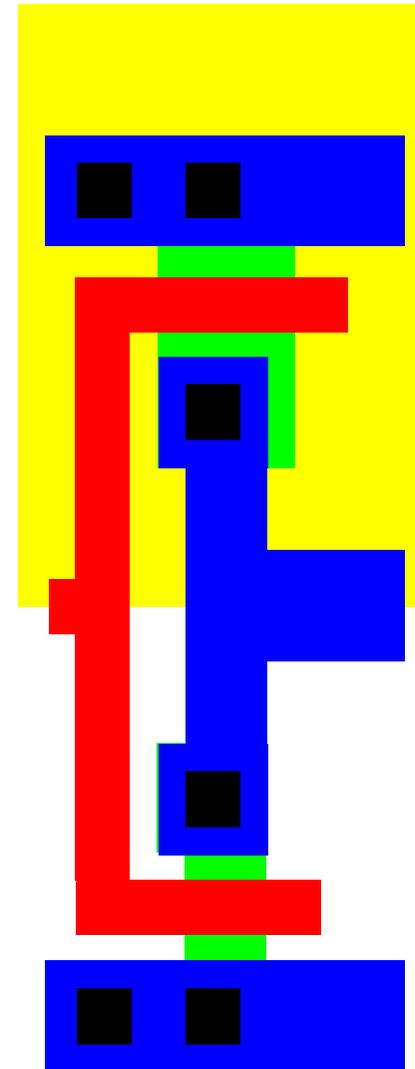
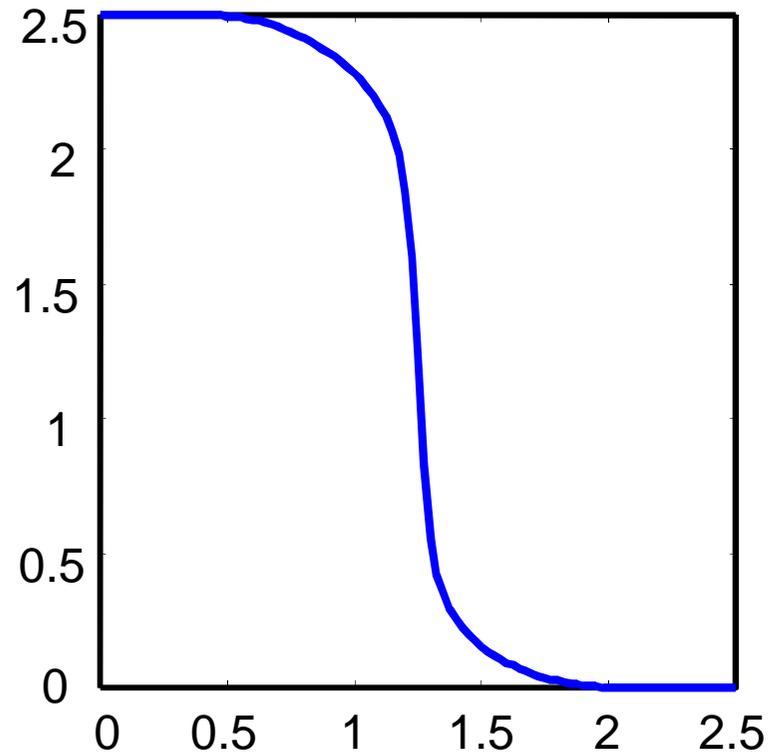


# Module 4 CMOS INVERTER



# Course Material for Inverter

## Chapter 5, 2nd ed.

**P = primair, I = Illustratie, O = overslaan**

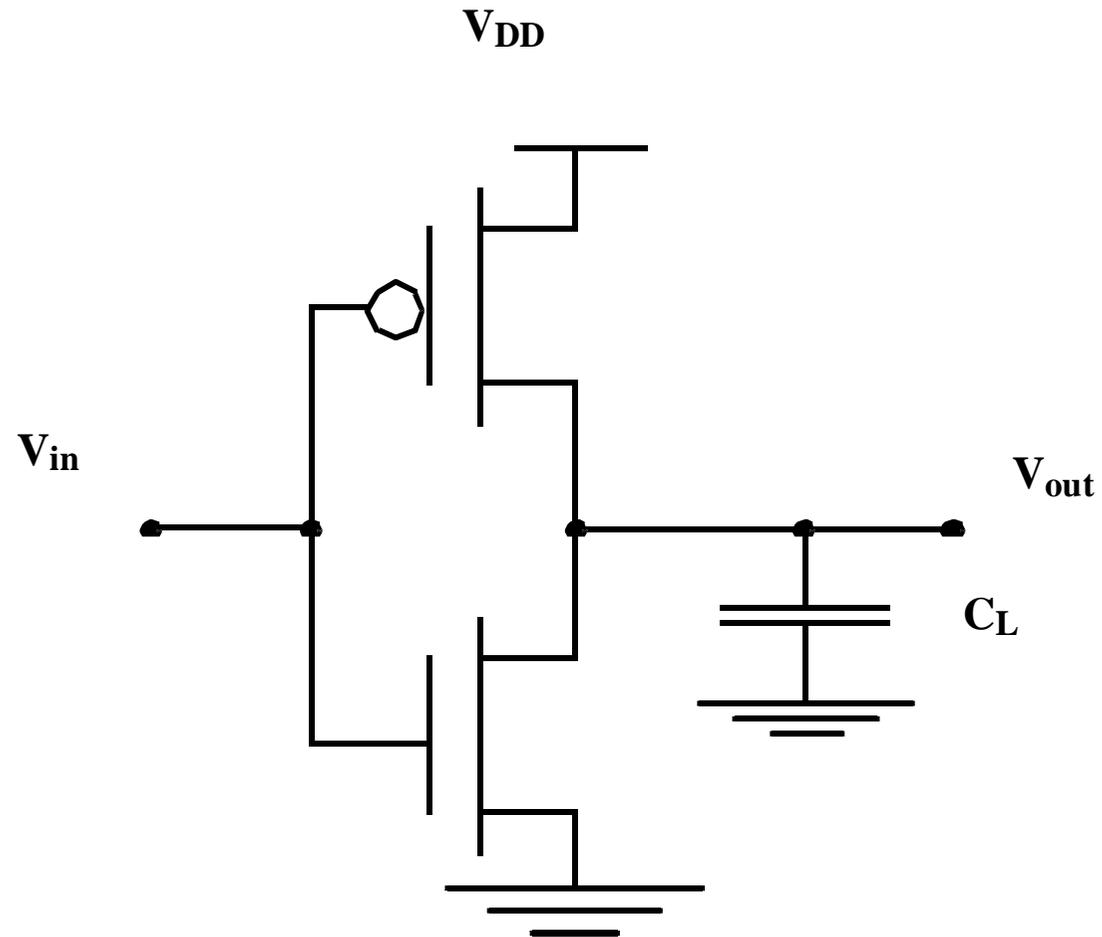
<b>P</b>	<b>5.1</b>	<b>Introduction</b>	<b>180</b>
<b>P</b>	<b>5.2</b>	<b>The Static CMOS inverter - intuitive</b>	<b>181 – 184</b>
<b>P</b>	<b>1.3.2</b>	<b>Functionality and Robustness</b>	<b>18 – 27</b>
<b>P</b>	<b>5.3</b>	<b>Evaluating the Robustness ...</b>	<b>184 – 191</b>
<b>I</b>	<b>5.3.3</b>	<b>Robustness Revisited</b>	<b>191 – 193</b>
<b>P</b>	<b>1.3.3</b>	<b>Performance</b>	<b>27 – 30</b>
<b>I</b>	<b>5.4</b>	<b>Performance of the CMOS inverter</b>	<b>193 – 213</b>
<b>P</b>	<b>1.3.4</b>	<b>Power and Energy Consumption</b>	<b>30 – 31</b>
<b>I</b>	<b>5.5</b>	<b>Power, Energy, and Energy-Delay</b>	<b>213 – 223</b>
<b>O</b>	<b>5.5.2</b>	<b>Static Consumption</b>	<b>223 – 225</b>
<b>O</b>	<b>5.5.3</b>	<b>Putting it All Together</b>	<b>225 – 227</b>
<b>O</b>	<b>5.5.4</b>	<b>Analyzing Power Consumption using SPICE</b>	<b>227 – 229.</b>
<b>O</b>	<b>5.6</b>	<b>Perspective: Technology scaling...</b>	<b>229 – 231</b>
<b>P</b>	<b>5.7</b>	<b>Summary</b>	<b>232 – 233</b>

**+Primair: pp. 214-215**

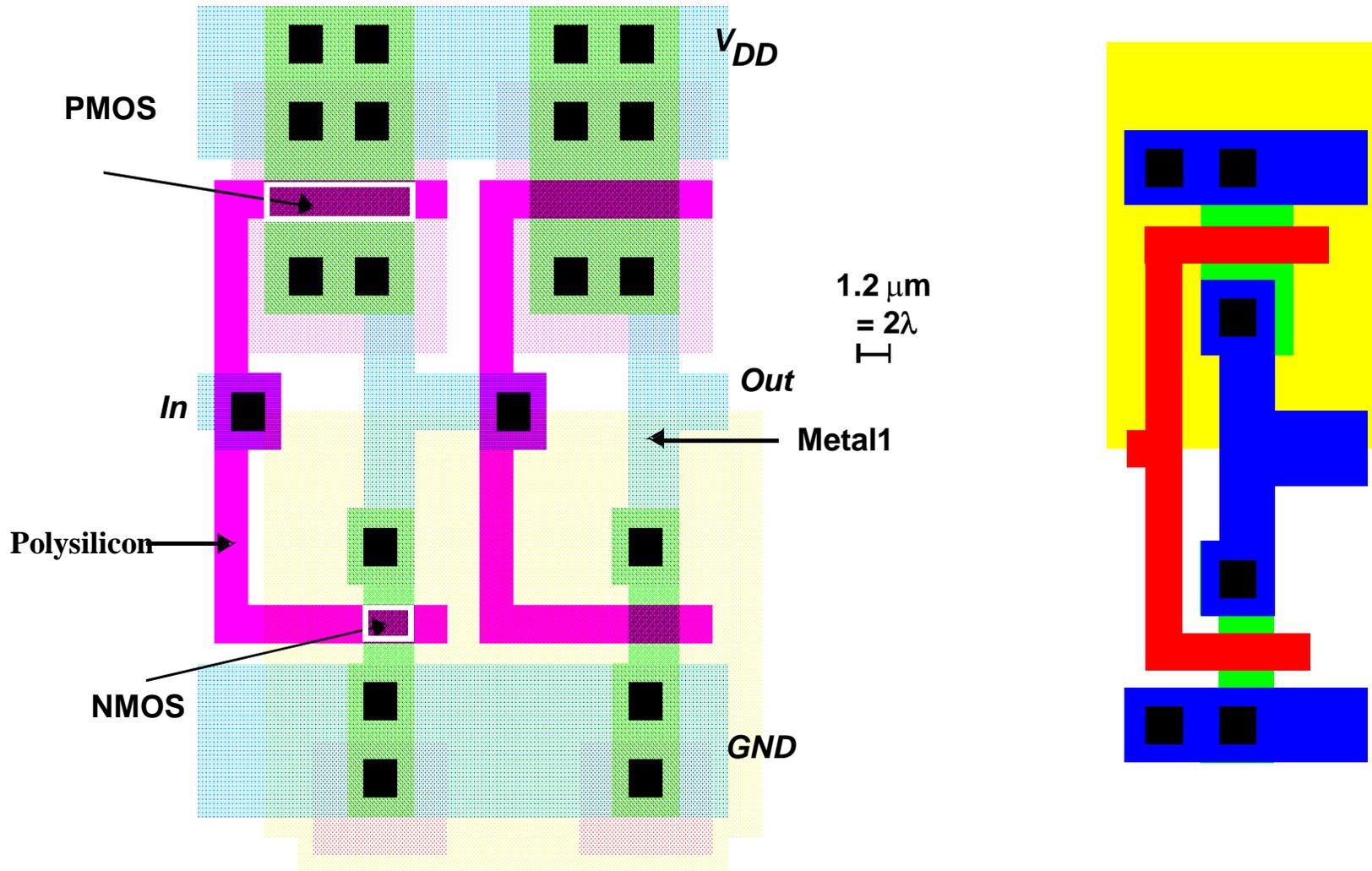
# The CMOS Inverter - Outline

- **First Glance**
- **Digital Gate Characterization**
- **Static Behavior (Robustness)**
  - **VTC**
  - **Switching Threshold**
  - **Noise Margins**
- **Dynamic Behavior (Performance)**
  - **Capacitances**
  - **Delay**
- **Power**
  - **Dynamic Power, Static Power, Metrics**

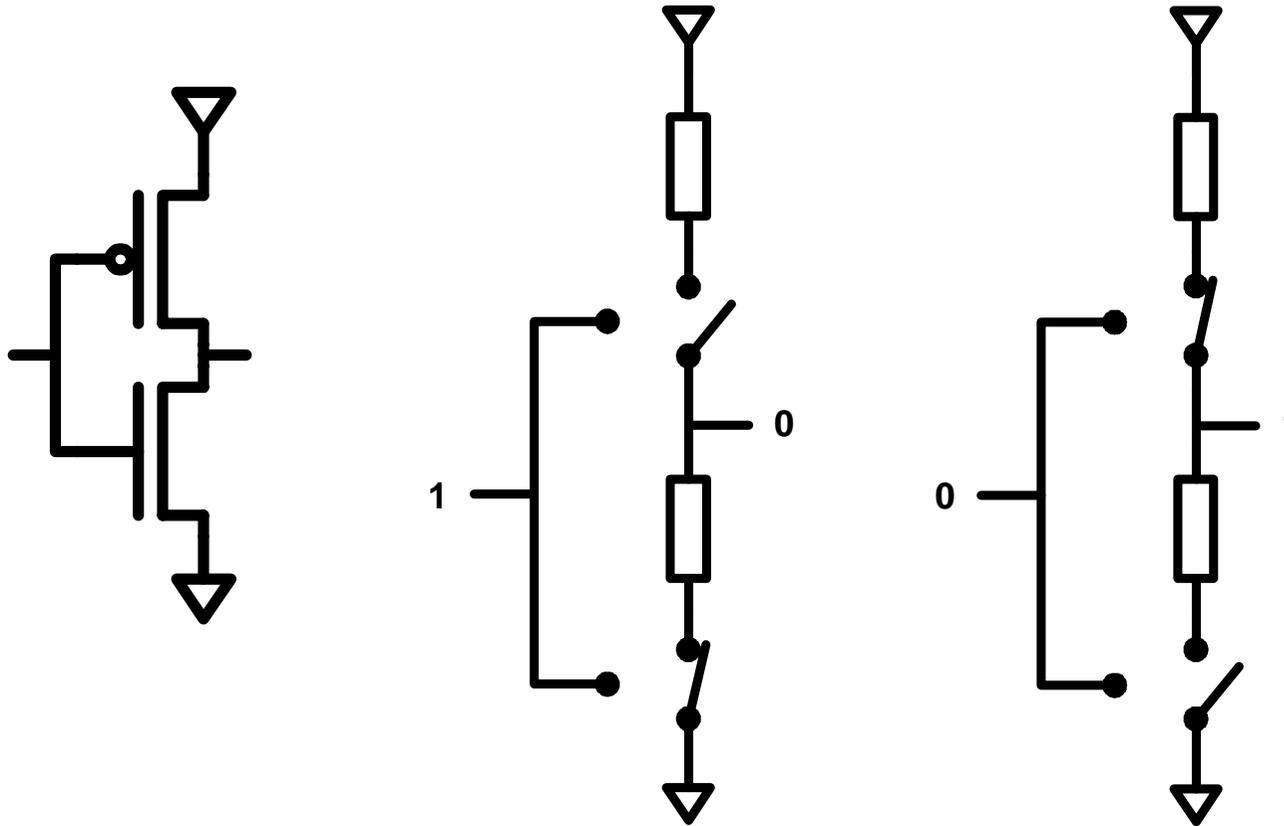
# The CMOS Inverter: A First Glance



# CMOS Inverters (1)



# CMOS Inverter Operation Principle



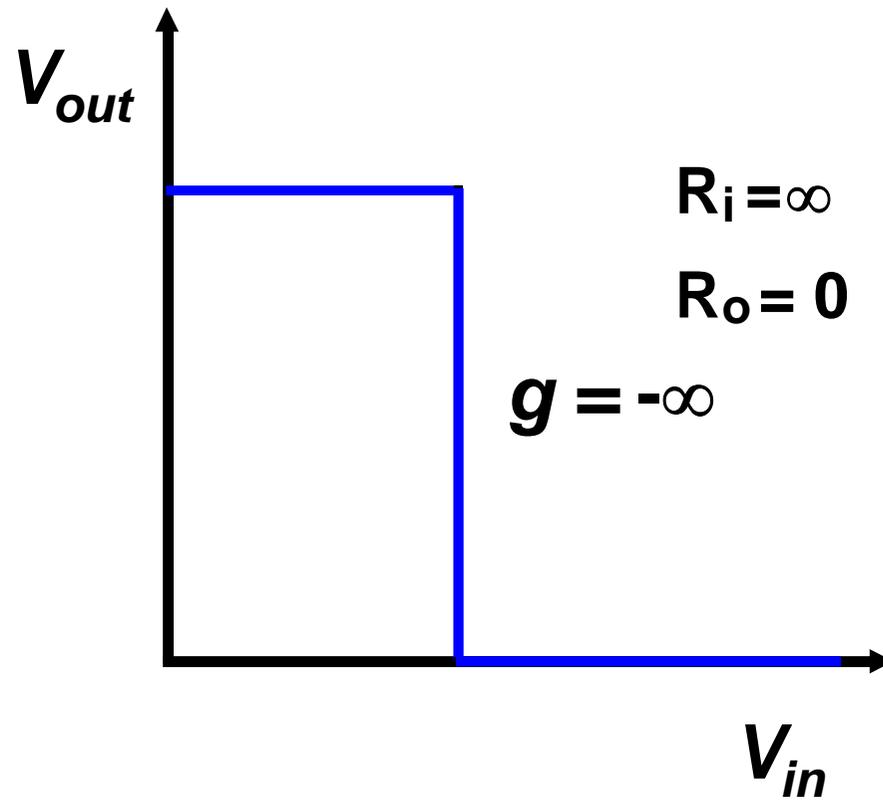
$$V_{OH} = V_{DD} \quad V_{OL} = 0$$



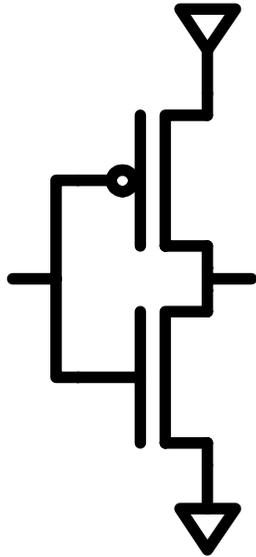
# Digital Gate Fundamental Parameters

- **Functionality**
- **Reliability, Robustness**
- **Area**
- **Performance**
  - **Speed (delay)**
  - **Power Consumption**
  - **Energy**

# The Ideal Inverter

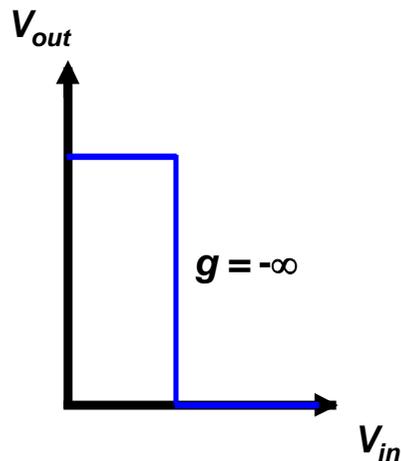


# Static CMOS Properties.



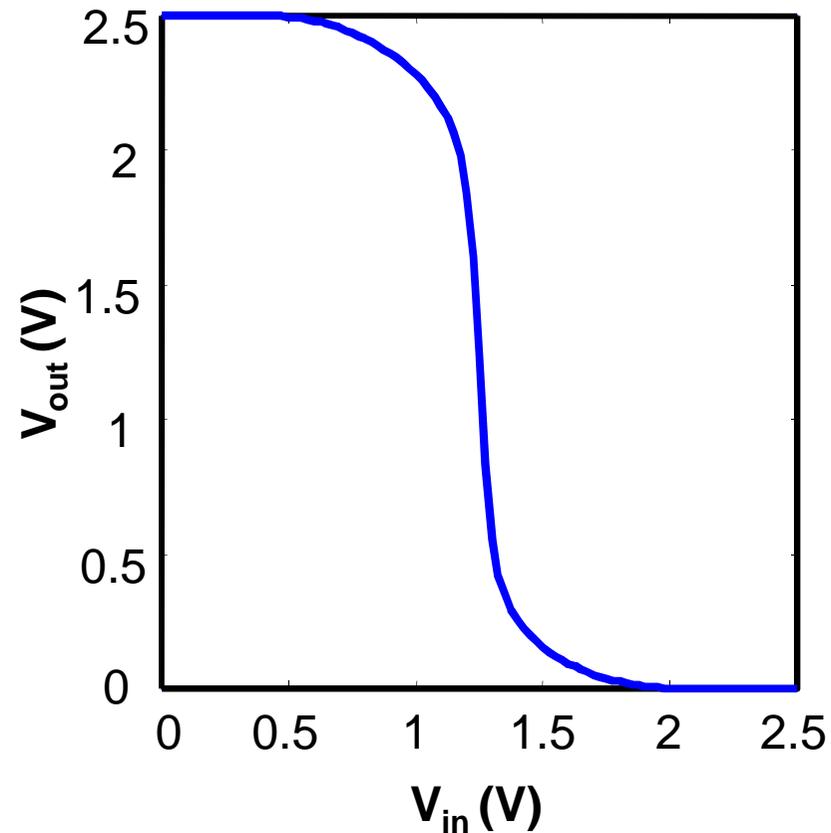
Basic inverter belongs to class of **static circuits**: output always connected to either  $V_{DD}$  or  $V_{SS}$ . **Not ideal but:**

- **Rail to rail** voltage swing
- **Ratio less** design
- **Low output impedance**
- **Extremely high input impedance**
- **No static power dissipation**
- **Good noise properties/margins**

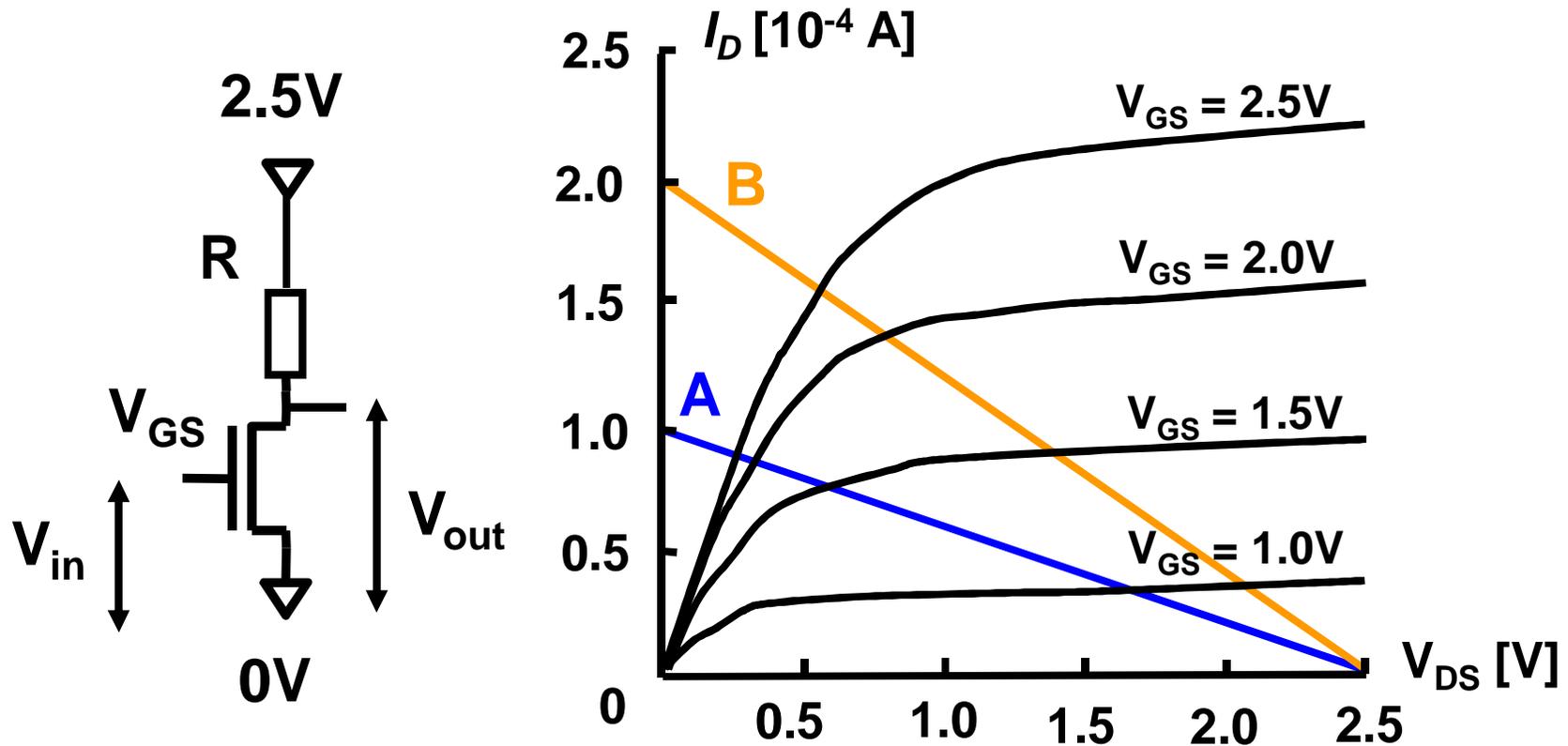


**Exercise:** prioritize the list above

# Voltage Transfer Characteristic (VTC)



# Load Line (Ckt Theory)



## Exercise:

The **blue** load line A corresponds to  $R =$

The **orange** load line B corresponds to  $R =$

With load line A and  $V_{GS} = 1V$ ,  $V_{out} =$

Draw a graph  $V_{out}(V_{in})$  for load line A and B

# PMOS Load Lines

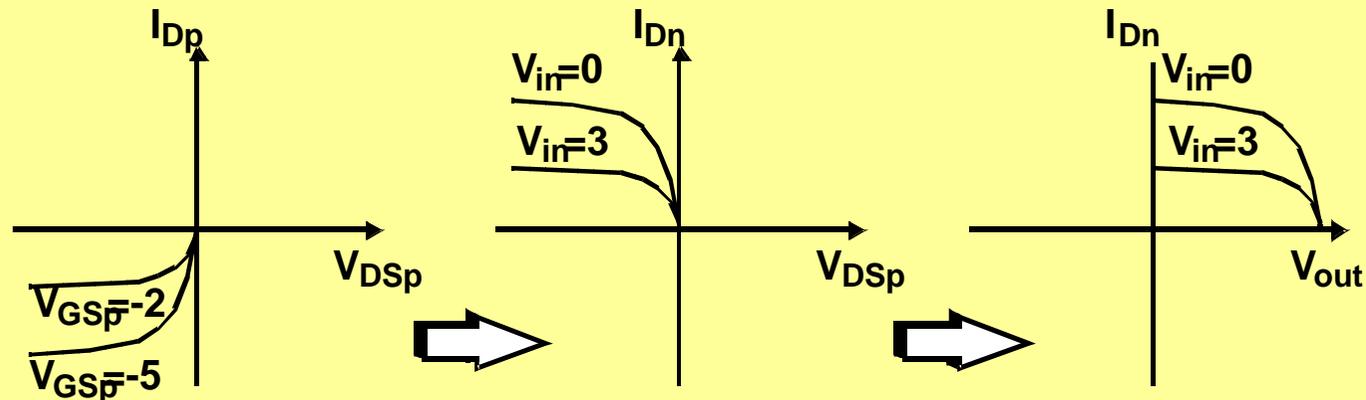
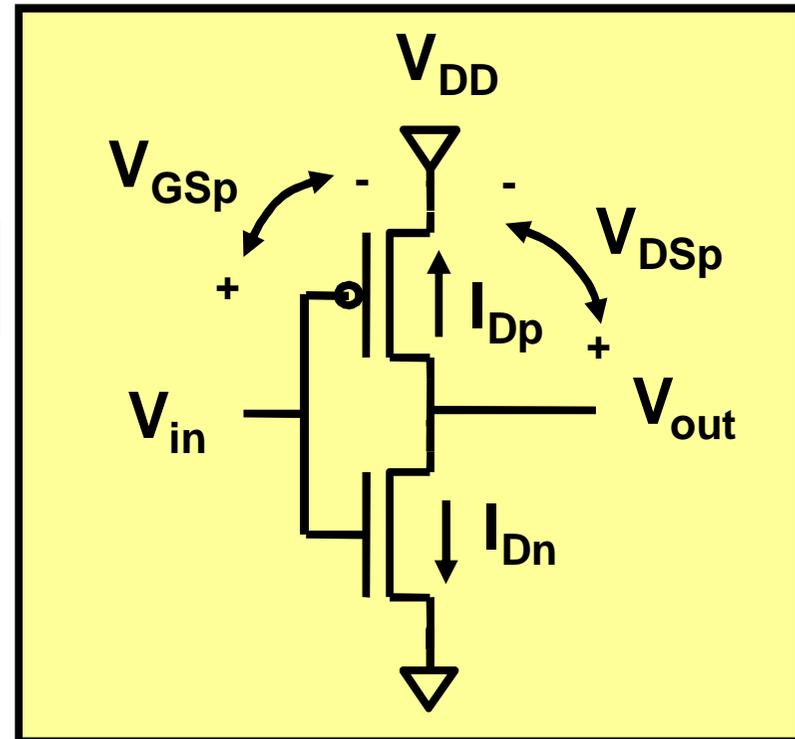
**Goal:** Combine  $I_{Dn}$  and  $I_{Dp}$  in one graph

**Kirchoff:**

$$V_{in} = V_{DD} + V_{GSp}$$

$$I_{Dn} = -I_{Dp}$$

$$V_{out} = V_{DD} + V_{DSp}$$



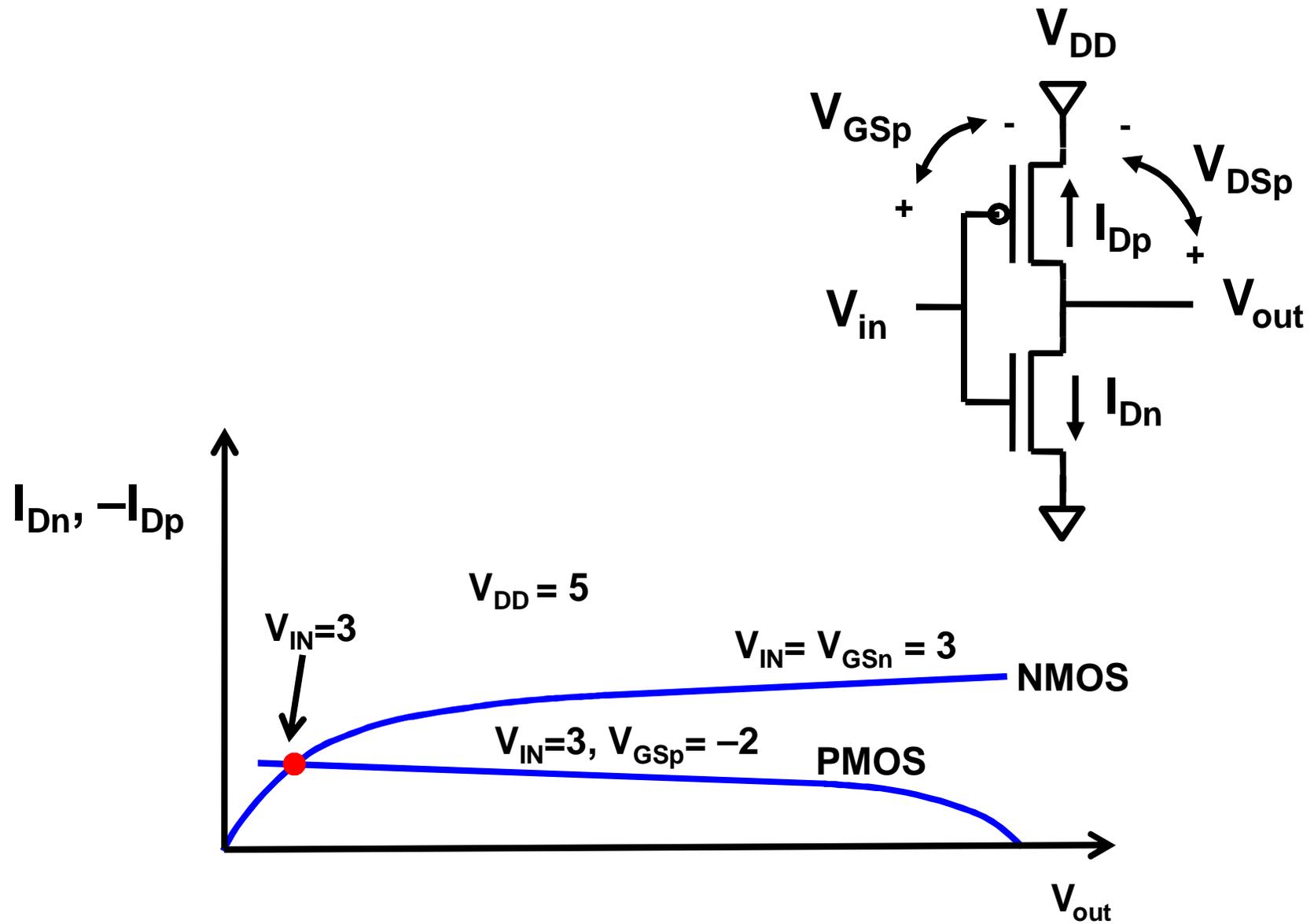
**Example:**  $V_{DD}=5V$

$$V_{in} = V_{DD} + V_{GSp}$$

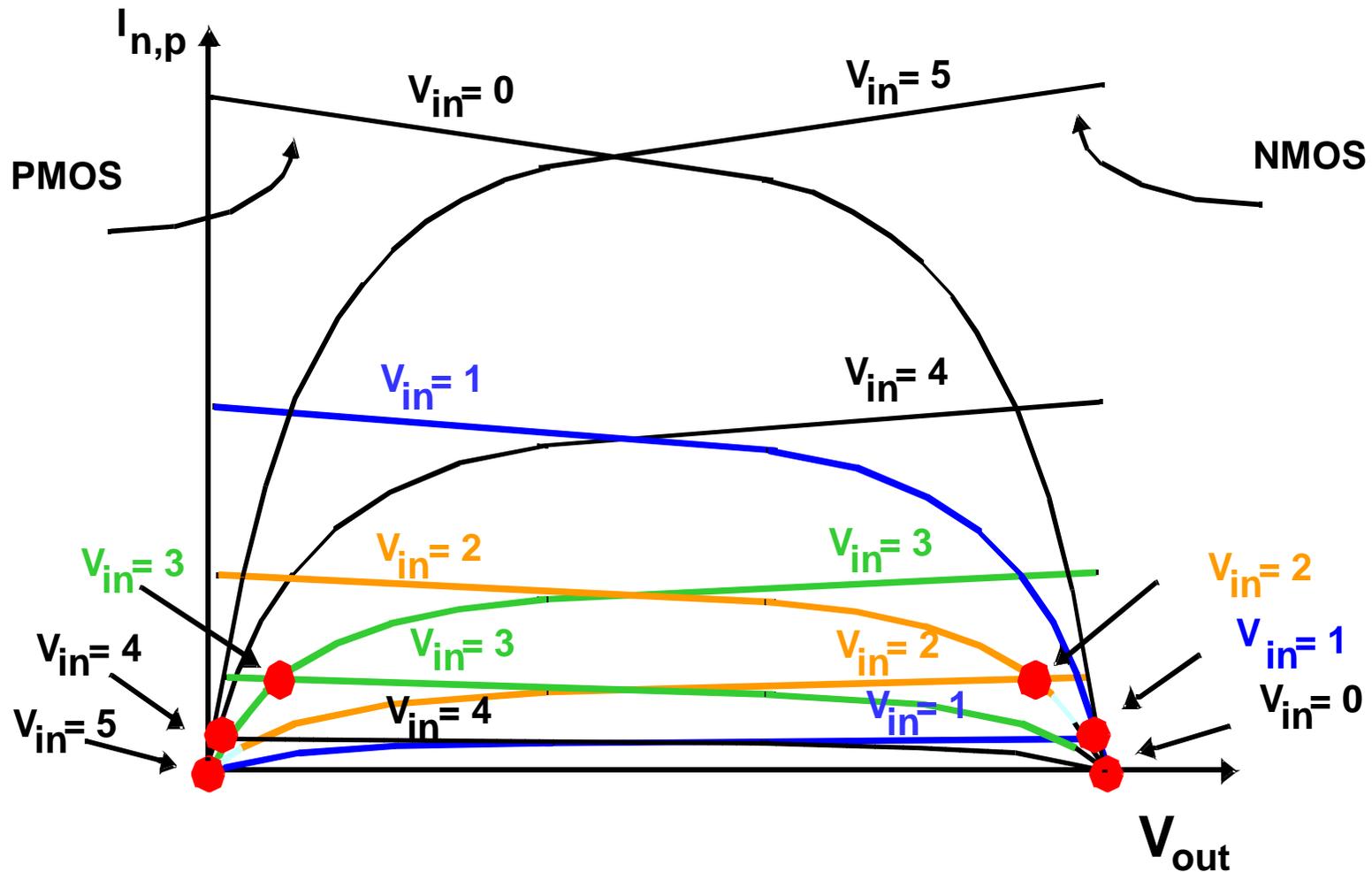
$$I_{Dn} = -I_{Dp}$$

$$V_{out} = V_{DD} + V_{DSp}$$

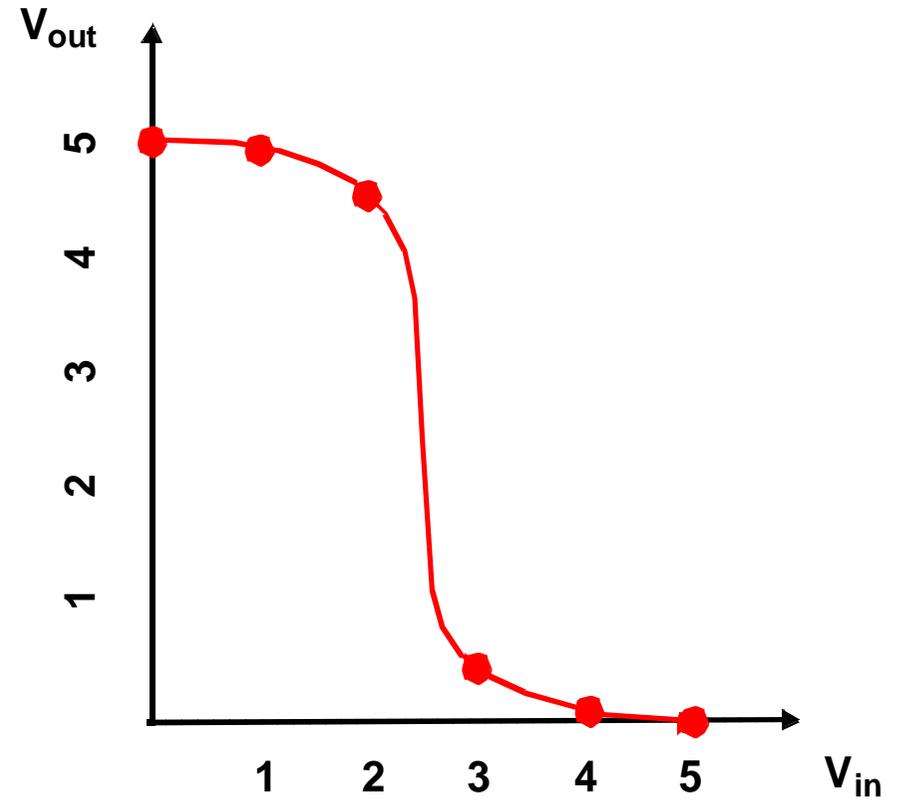
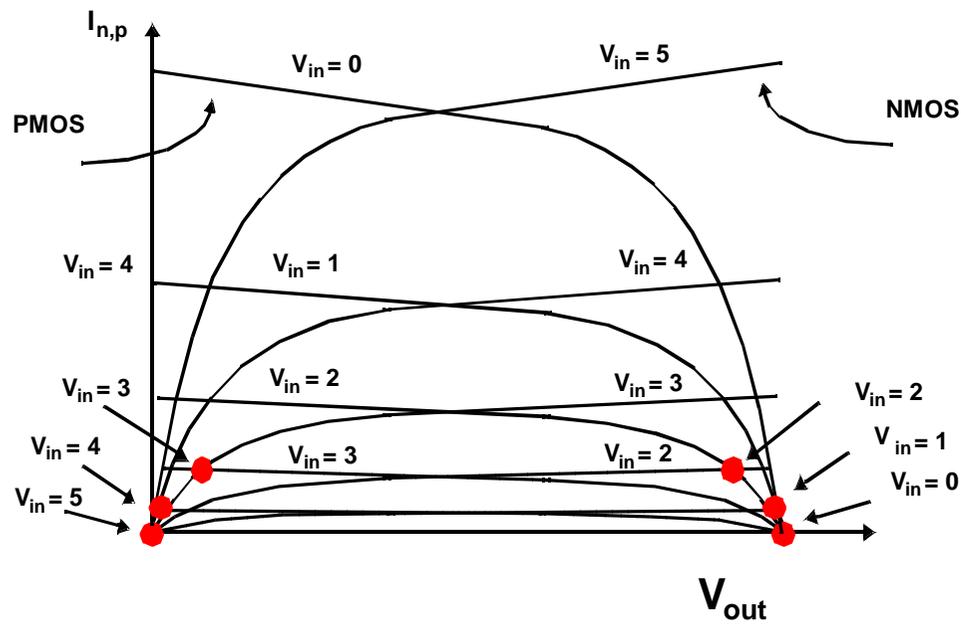
# CMOS Inverter Load Characteristics



# CMOS Inverter Load Characteristics

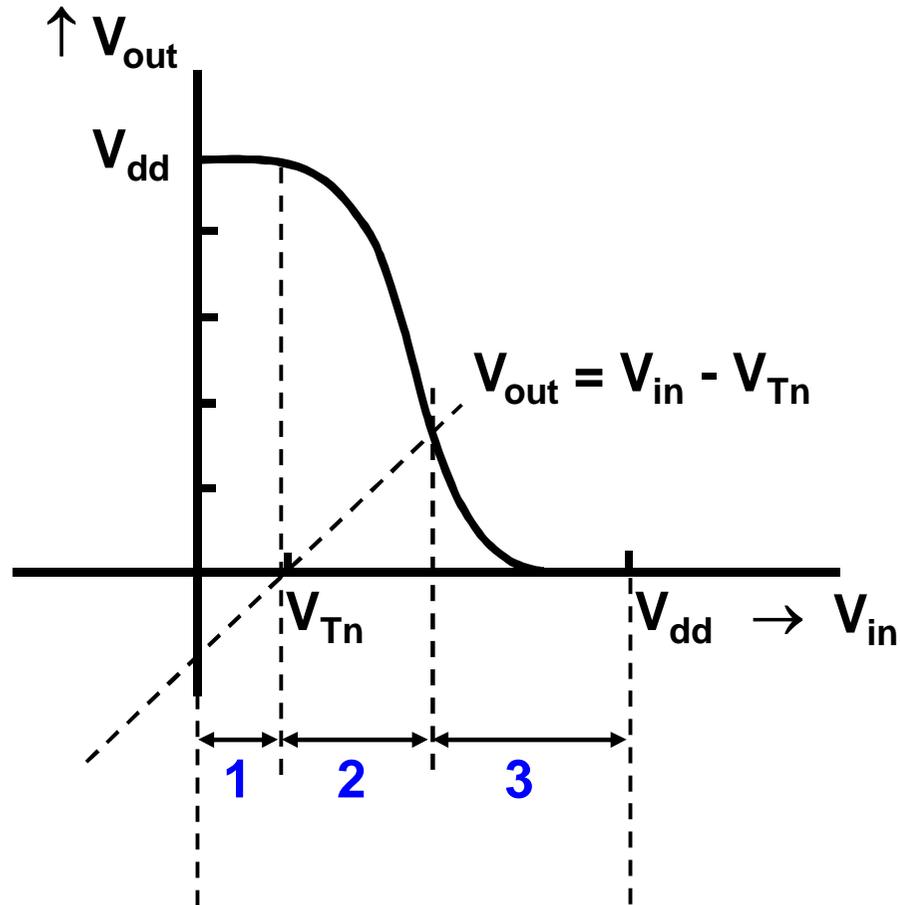


# CMOS Inverter VTC.



# NMOS Operating Conditions

Need to know for proper dimensioning, analysis of noise margin, etc.



## NMOS

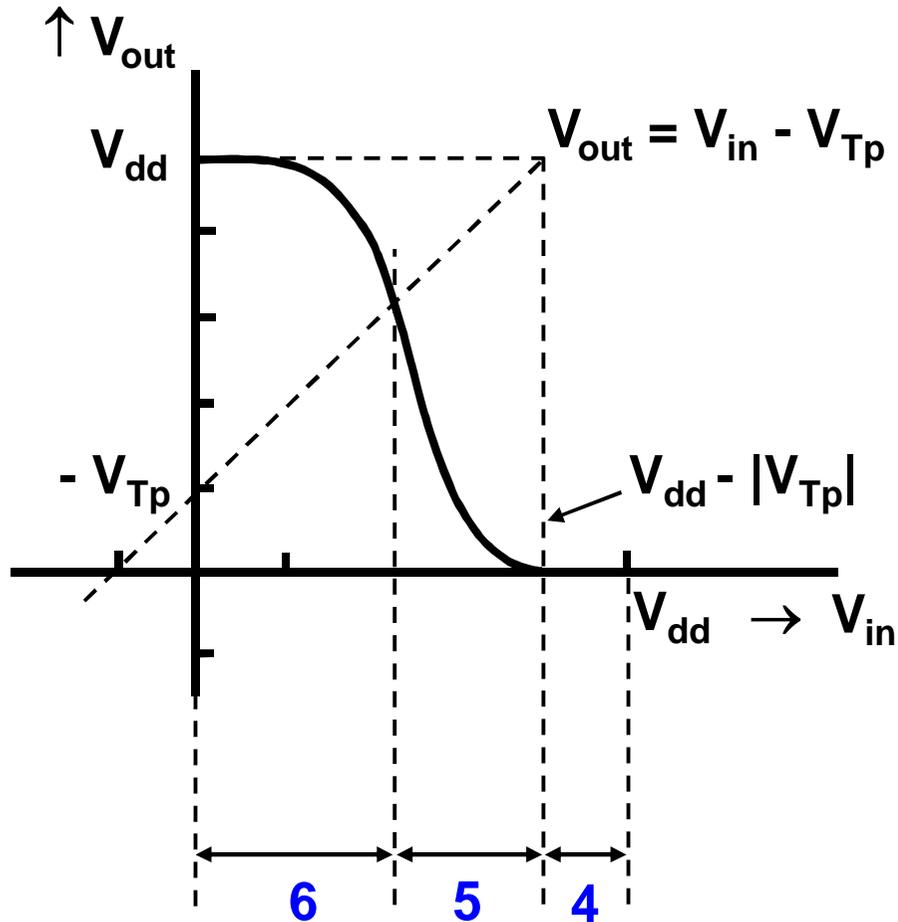
1  $V_{in} = V_{GS} < V_{Tn} \Rightarrow$  **off**

2  $V_{out} > V_{in} - V_{Tn}$   
 $V_{DS} > V_{GS} - V_{Tn}$   
 $V_{GD} < V_{Tn} \Rightarrow$  **saturation**

3  $V_{out} < V_{in} - V_{Tn} \Rightarrow$  **resistive**

# PMOS Operating Conditions

Need to know for proper dimensioning, analysis of noise margin, etc.



## PMOS

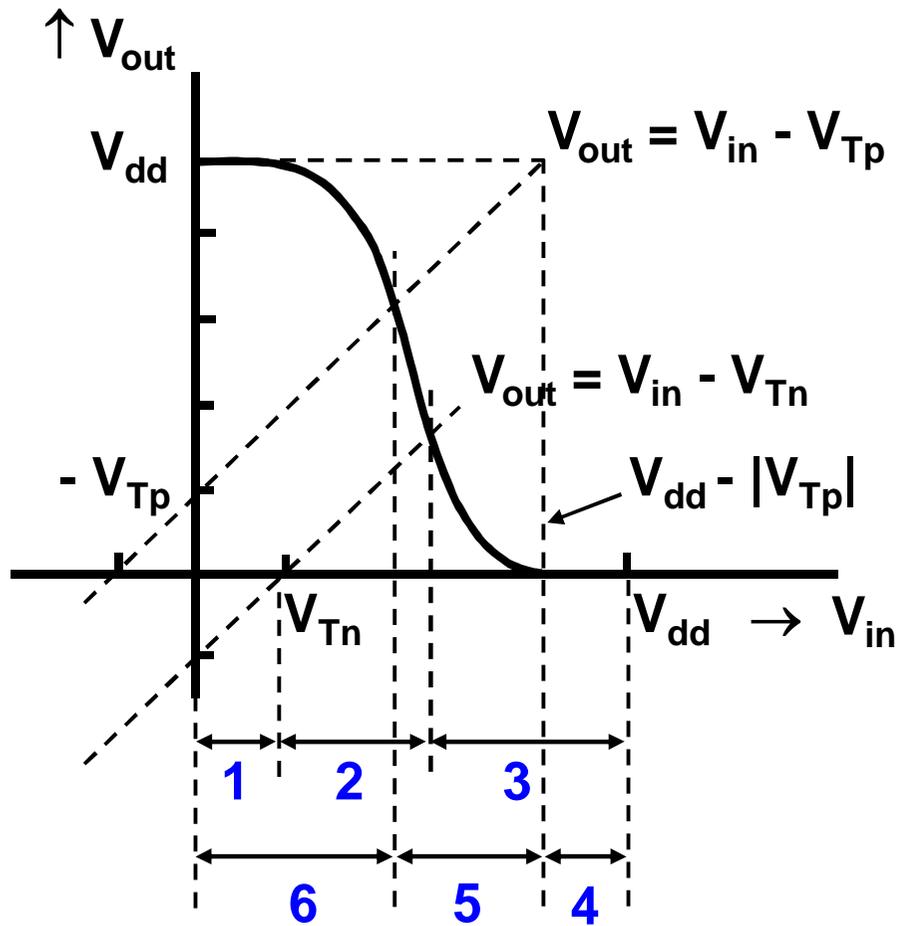
4  $V_{in} > V_{DD} + V_{Tp} \Rightarrow$  **off**

5  $V_{out} < V_{in} - V_{Tp} \Rightarrow$  **saturation**

6  $V_{out} > V_{in} - V_{Tp} \Rightarrow$  **resistive**

**Exercise: check results for PMOS**

# Operating Conditions.



**NMOS 1 off**

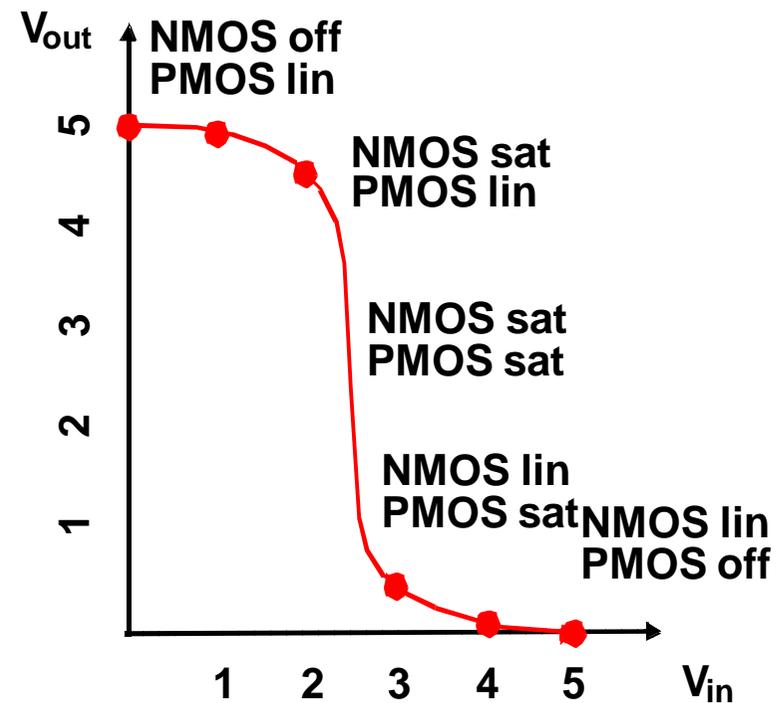
**2 saturation**

**3 resistive**

**PMOS 4 off**

**5 saturation**

**6 resistive**

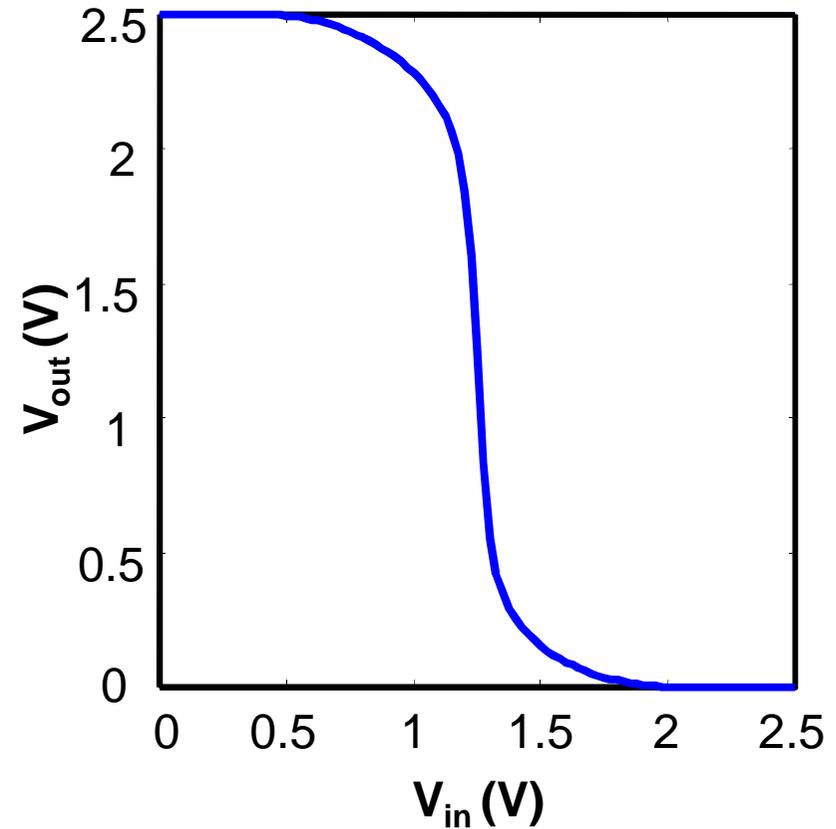
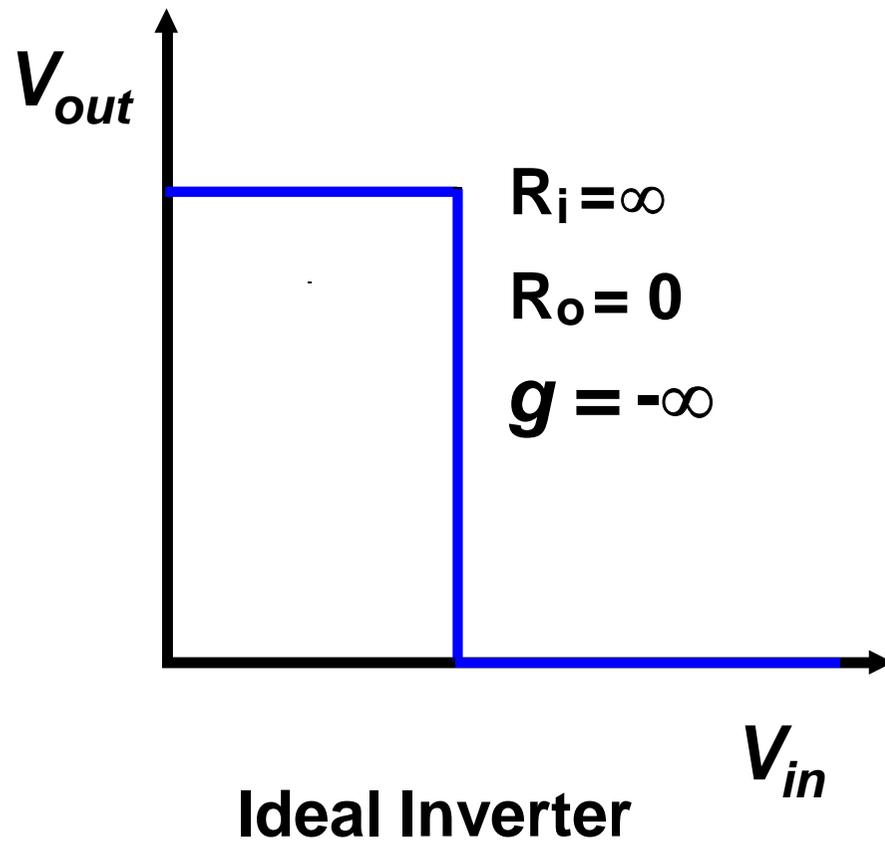


# Inverter Static Behavior

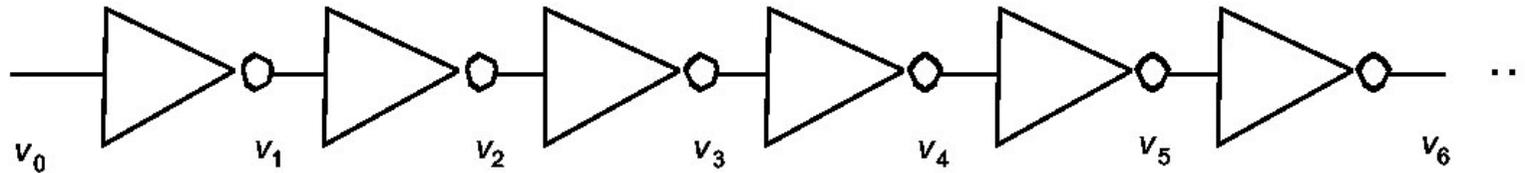
- Regeneration
- Noise margins
- Delay metrics



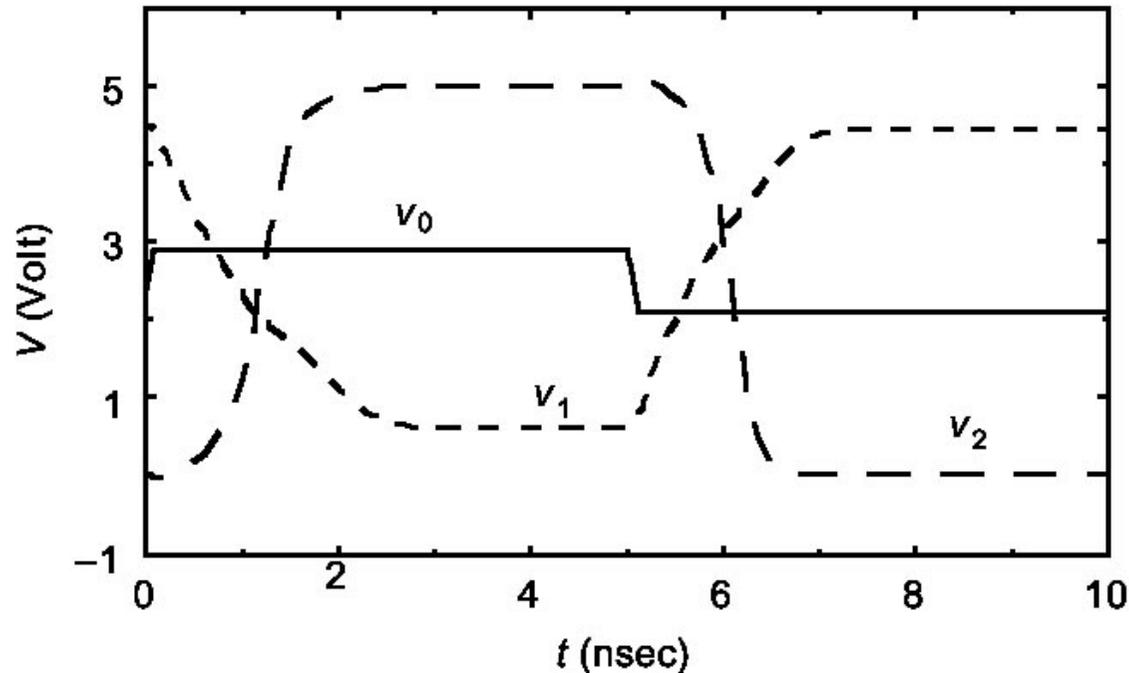
# The Realistic Inverter



# The Regenerative Property

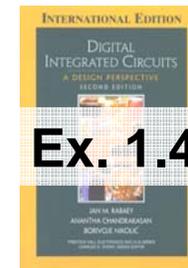


**A chain of inverters**

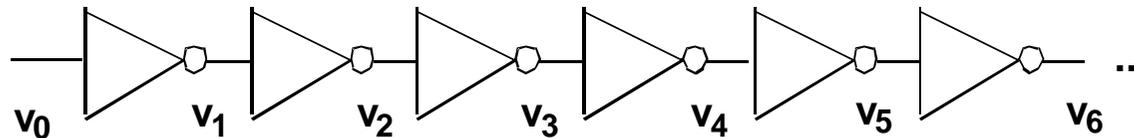


**Regenerative Property:** ability to regenerate (repair) a weak signal in a chain of gates

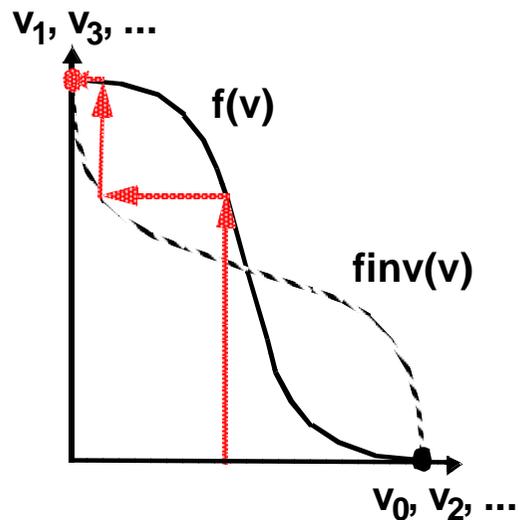
## The regenerative property



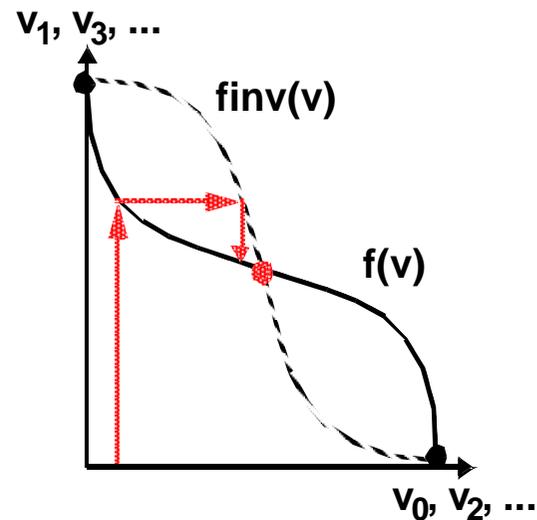
# The Regenerative Property (2)



(a) A chain of inverters.

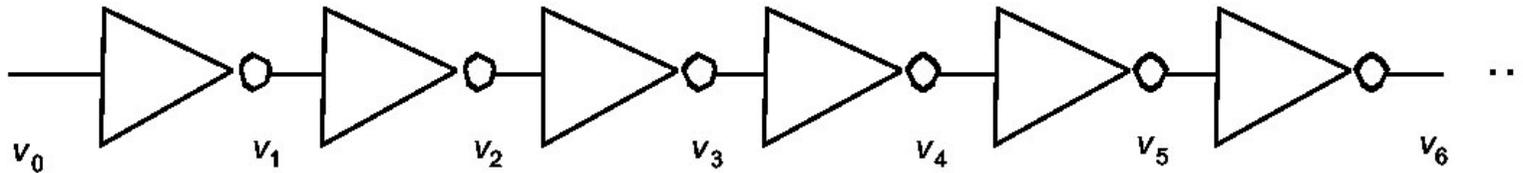


(b) Regenerative gate



(c) Non-regenerative gate

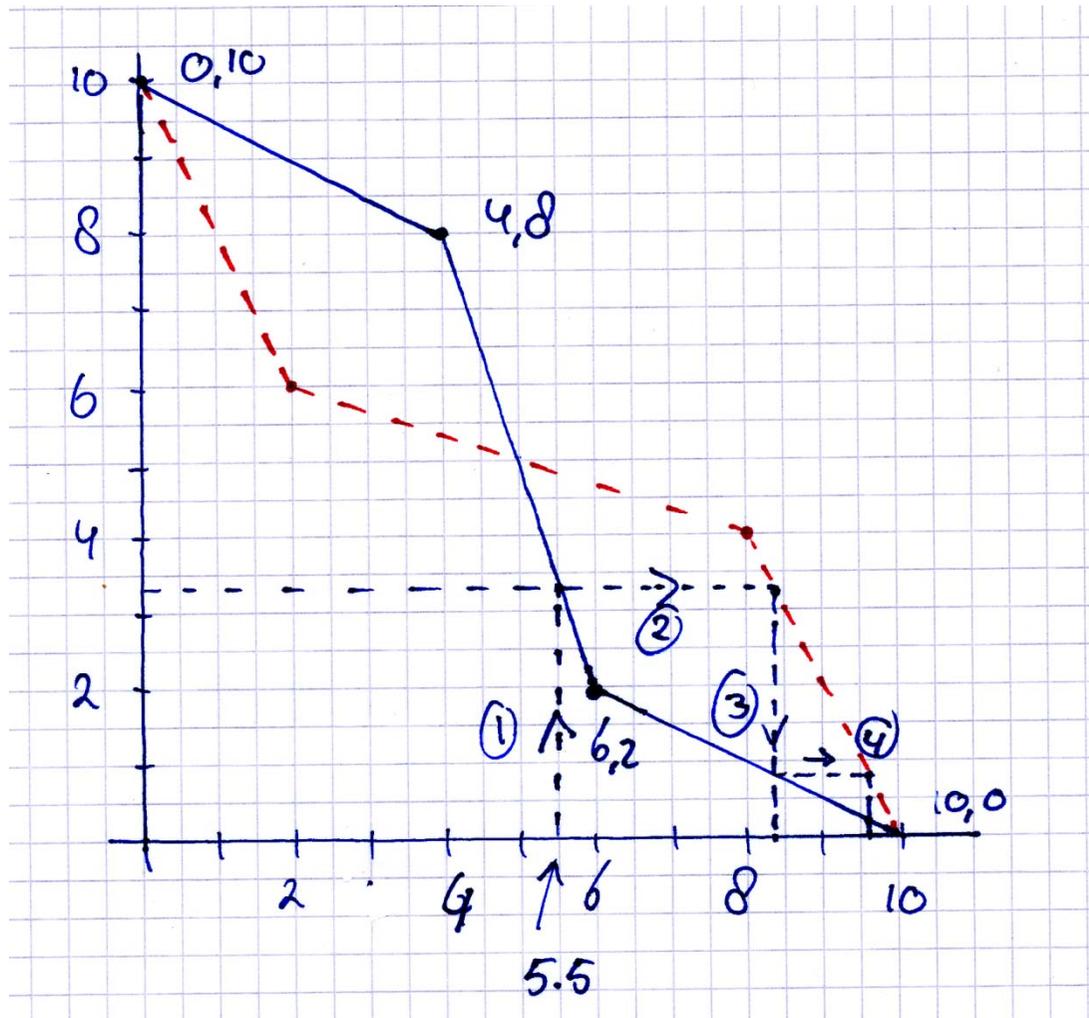
## The regenerative Property (3)



**Exercise:** what is the output voltage of a chain of 4 inverters with a piece-wise linear VTC passing through (0, 10), (4,8), (6,2) and (10,0) [Volt], as the result of an input voltage of 5.5 [Volt].

**Exercise:** discuss the behavior for an input of 5 [Volt]

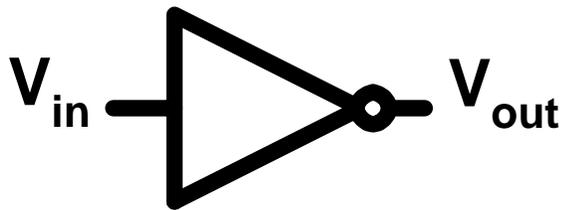
# Exercise Answer



**Ongeveer: 5.5 → 3.5 → 8.5 → 0.75 → 9.75**

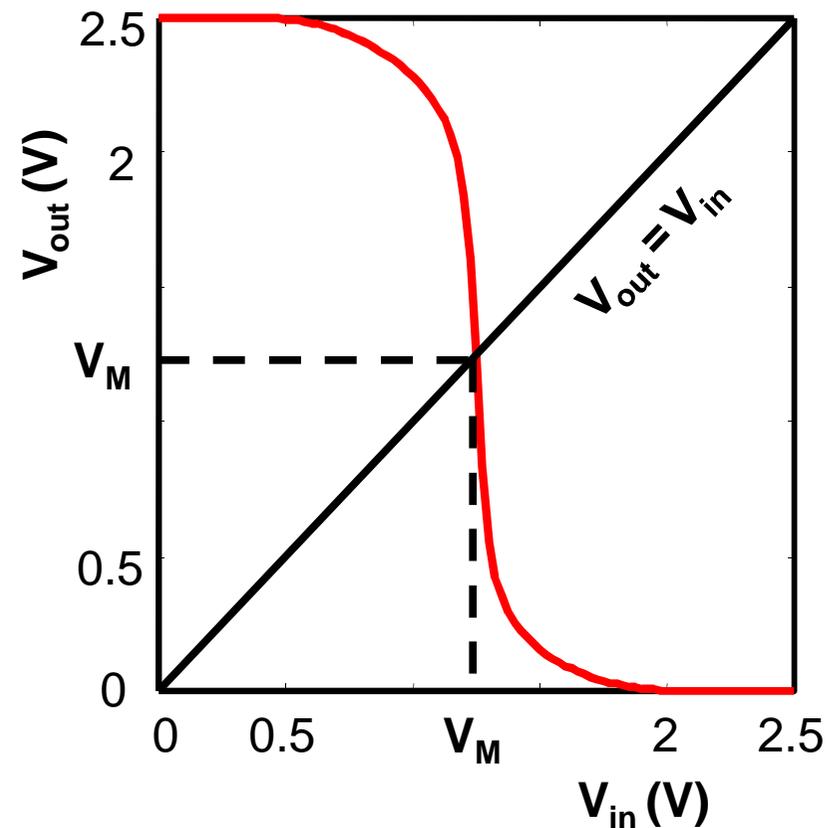
# Inverter Switching Threshold

- Not the device threshold  $V_m = f(R_{onn}, R_{onp})$
- Point of  $V_{in} = V_{out}$

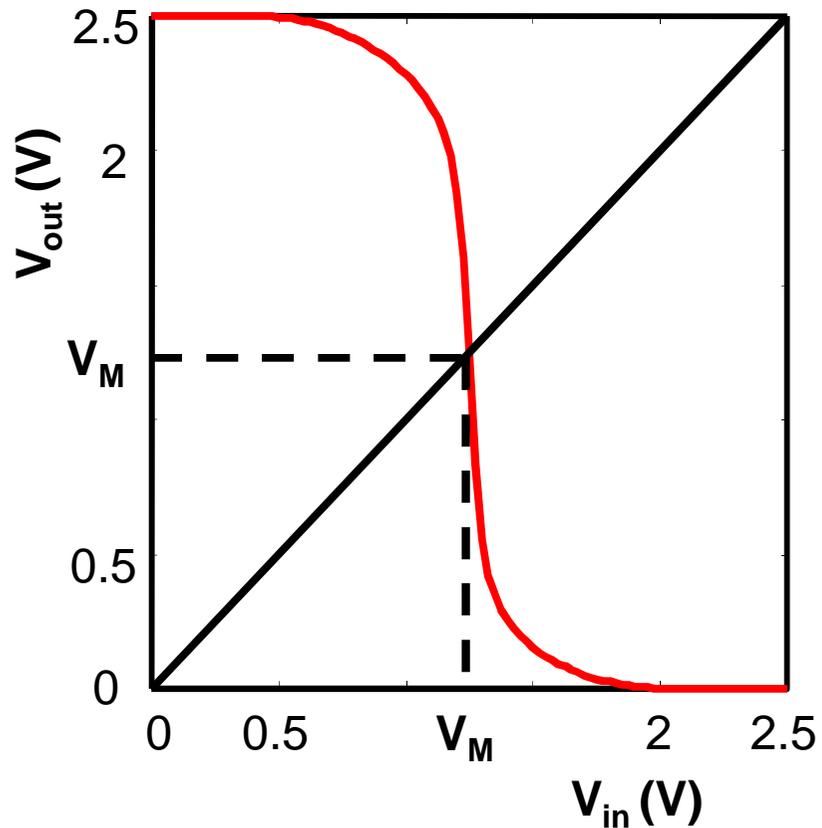


- Try to set  $W_n, L_n, W_p, L_p$  so that VTC is symmetric as this will improve noise margins

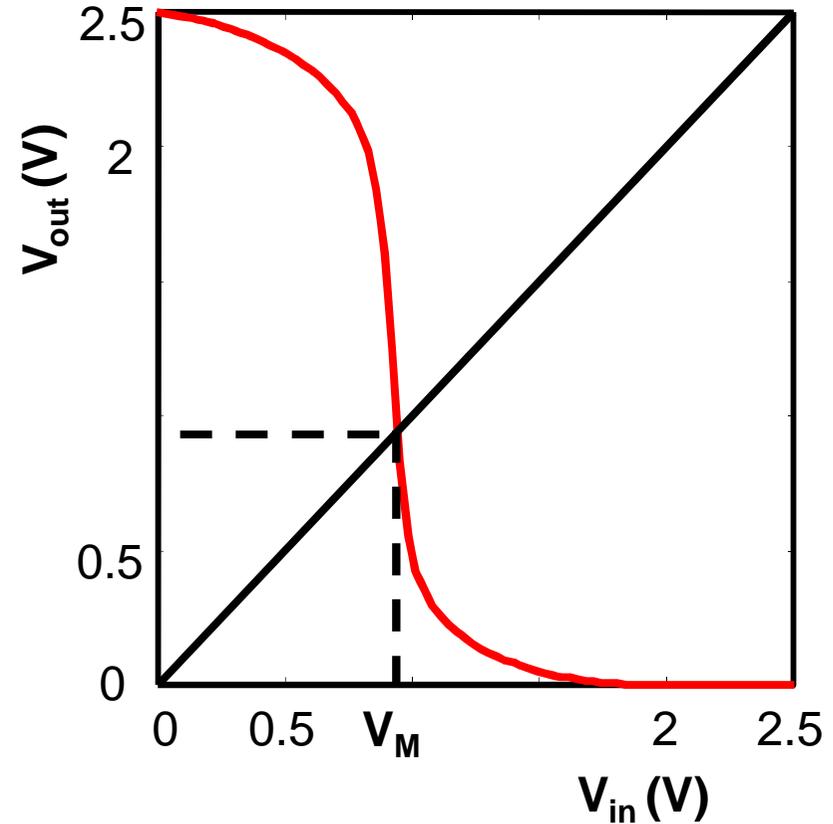
**optimize NMOS-PMOS ratio**



# Inverter Switching Threshold



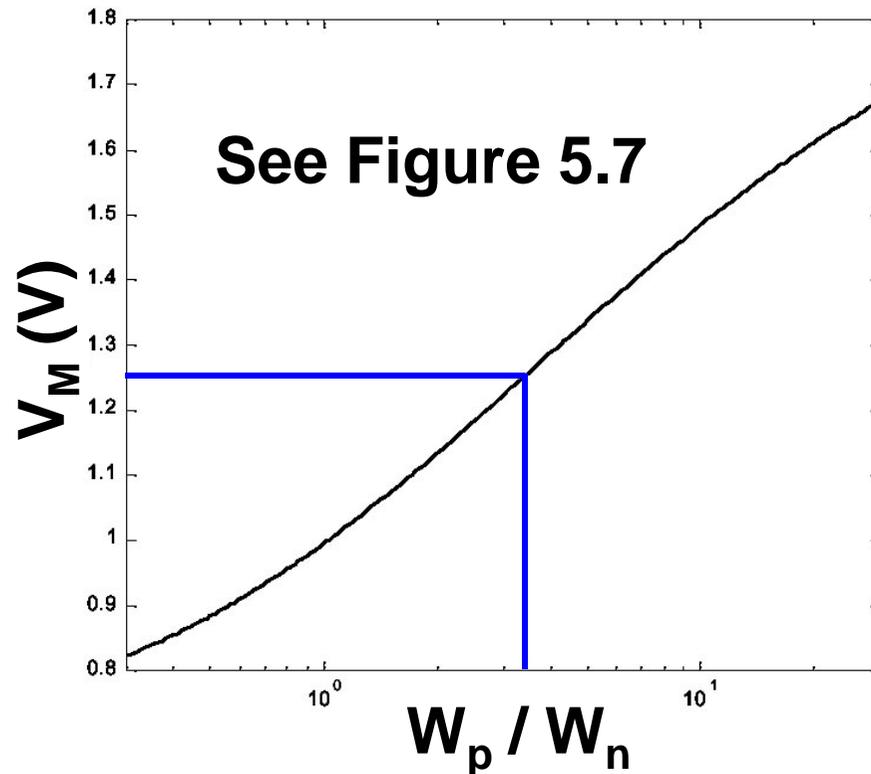
Balanced NMOS and PMOS sizes



Strong NMOS, Weak PMOS

$$V_M = f(W_n/W_p)$$

# Simulated Inverter Switching Threshold



## Electrical Design Rule

$$W_p \approx 2.5 W_n$$

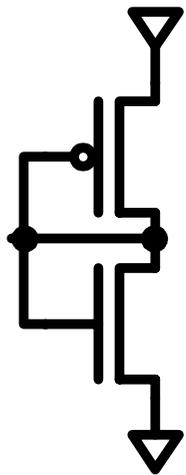
- Assumes  $L_p = L_n$
- Should be applied consistently

- Symmetrical VTC  $\Rightarrow V_m \approx \frac{1}{2} V_{DD} \Rightarrow W_p/W_n \approx$
- In practice: choose somewhat smaller value of  $W_p/W_n$
- Why?

# Inverter Switching Threshold

## Analytical Derivation

- $V_M$  is  $V_{in}$  such that  $V_{in} = V_{out}$
- $V_{DS} = V_{GS} \Leftrightarrow V_{GD} = 0 \Rightarrow$  saturation
  - Assume  $V_{DSAT} < V_M - V_T$   
(velocity saturation)
  - Ignore channel length modulation  
(for simplicity – is it allowed?)
- $V_M$  follows from
  - $I_{DSATn}(V_M) = -I_{DSATp}(V_M)$
  - Q: Given desired value of  $V_M$ , what is the required W/L ratio?



# Inverter Switching Threshold

## Analytical Derivation (ctd)

$$I_{DSATn}(V_M) = -I_{DSATp}(V_M)$$

$$I_D = kV_{DSAT}(V_{GS} - V_T - V_{DSAT}/2)$$

$$\Leftrightarrow k_n V_{DSATn} (V_M - V_{Tn} - V_{DSATn}/2) = -k_p V_{DSATp} (V_M - V_{DD} - V_{Tp} - V_{DSATp}/2)$$

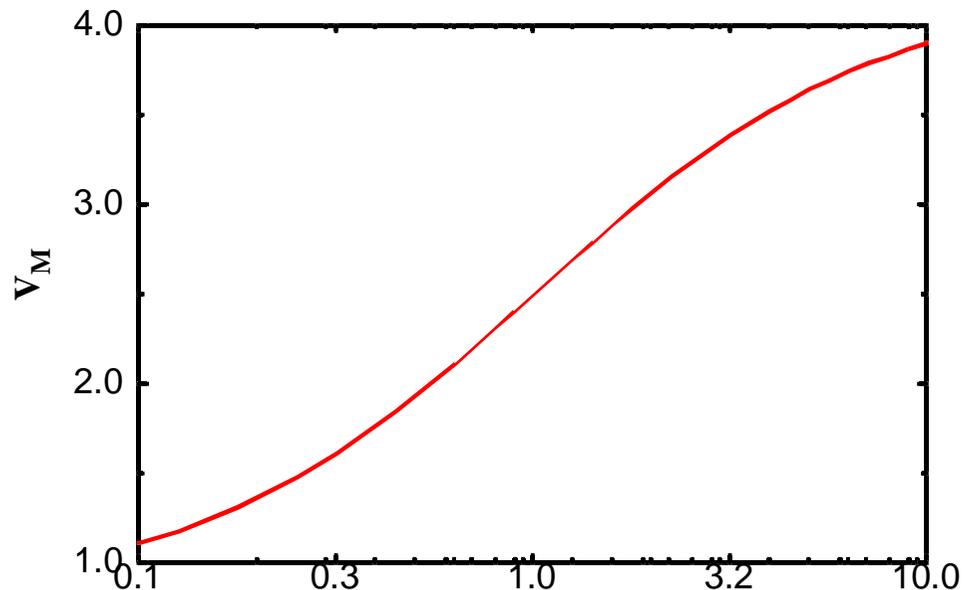
$$\Leftrightarrow \frac{k_p}{k_n} = \frac{-V_{DSATn} (V_M - V_{Tn} - V_{DSATn}/2)}{V_{DSATp} (V_M - V_{DD} - V_{Tp} - V_{DSATp}/2)} \quad k = \frac{W}{L} k'$$

$$\Rightarrow \frac{(W/L)_p}{(W/L)_n} = \left| \frac{k_n V_{DSATn} (V_M - V_{Tn} - V_{DSATn}/2)}{k_p V_{DSATp} (V_M - V_{DD} - V_{Tp} - V_{DSATp}/2)} \right|$$

- See Example 5.1:
- $(W/L)_p = 3.5 (W/L)_n$  for typical conditions and  $V_M = \frac{1}{2} V_{DD}$
- Usually:  $L_n = L_p$

# Inverter Switching Threshold w/o Velocity Saturation.

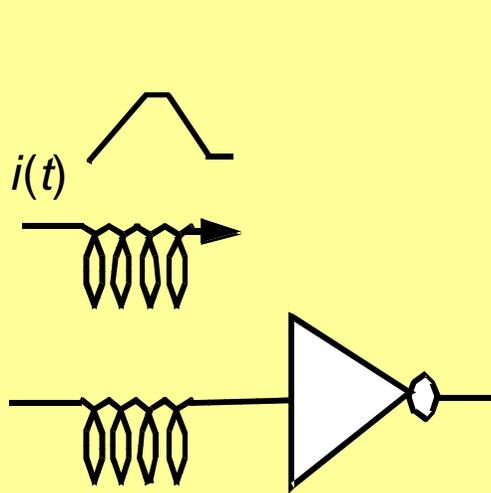
- Long channel approximation
- Applicable with low  $V_{DD}$



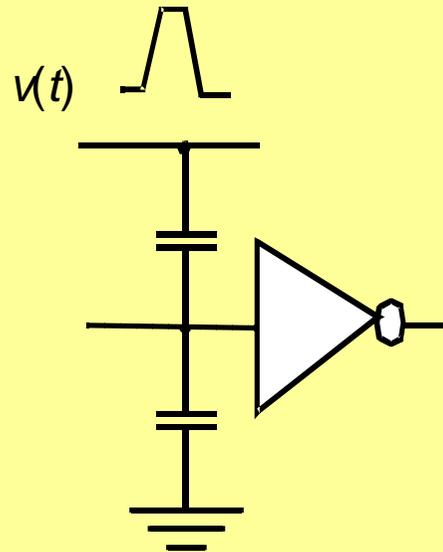
**Exercise (Problem 5.1):**  
derive  $V_M$  for long-  
channel approximation  
as shown below

$$V_M = \frac{r(V_{DD} - V_{Tp} + V_{Tn})}{1+r} \text{ with } r = \sqrt{\frac{-k_p}{k_n}}$$

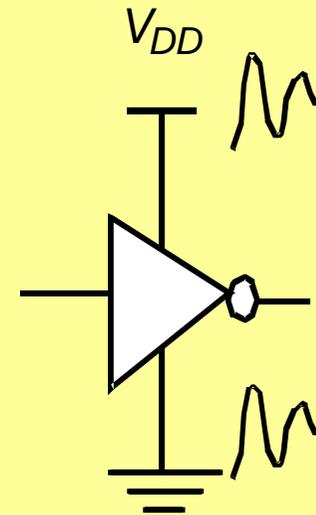
# Noise in Digital Integrated Circuits



(a) Inductive coupling



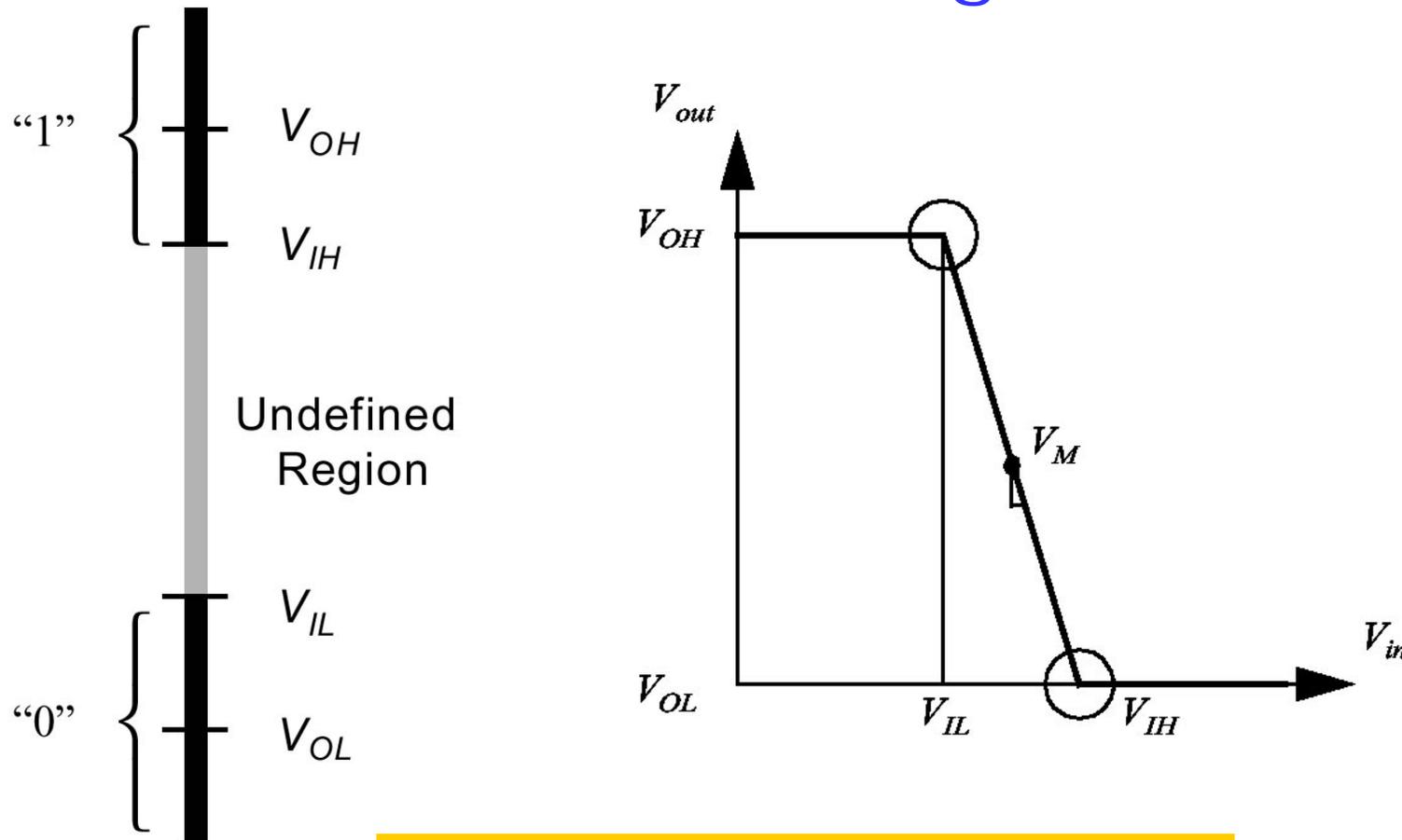
(b) Capacitive coupling



(c) Power and ground noise

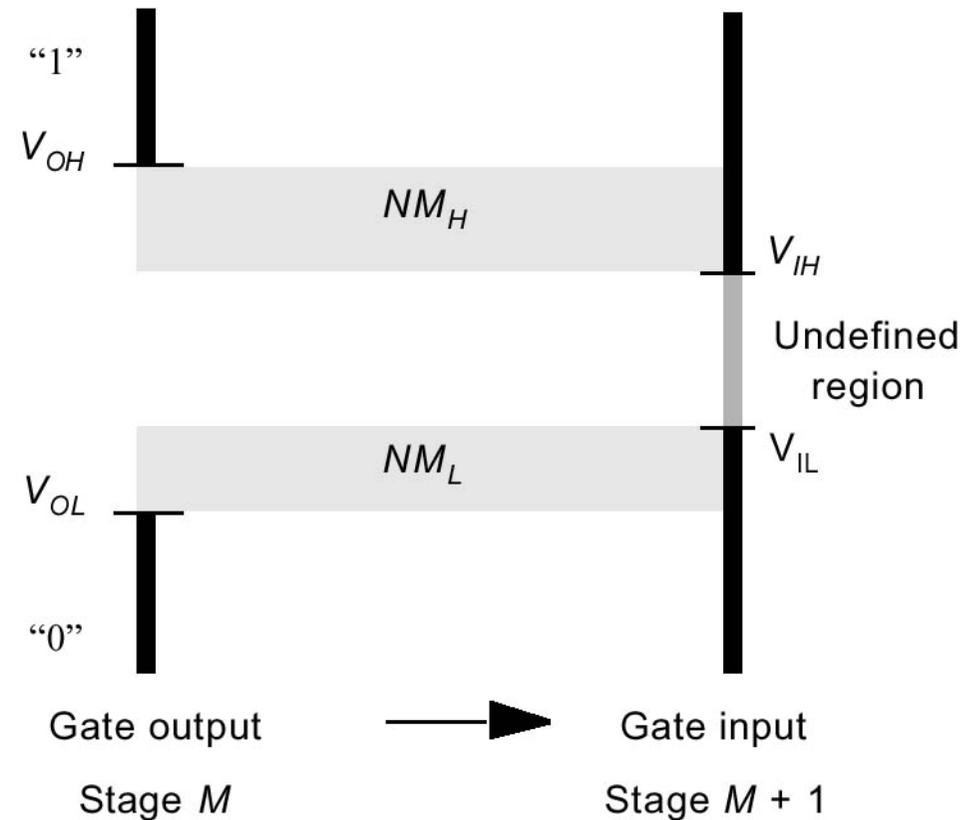
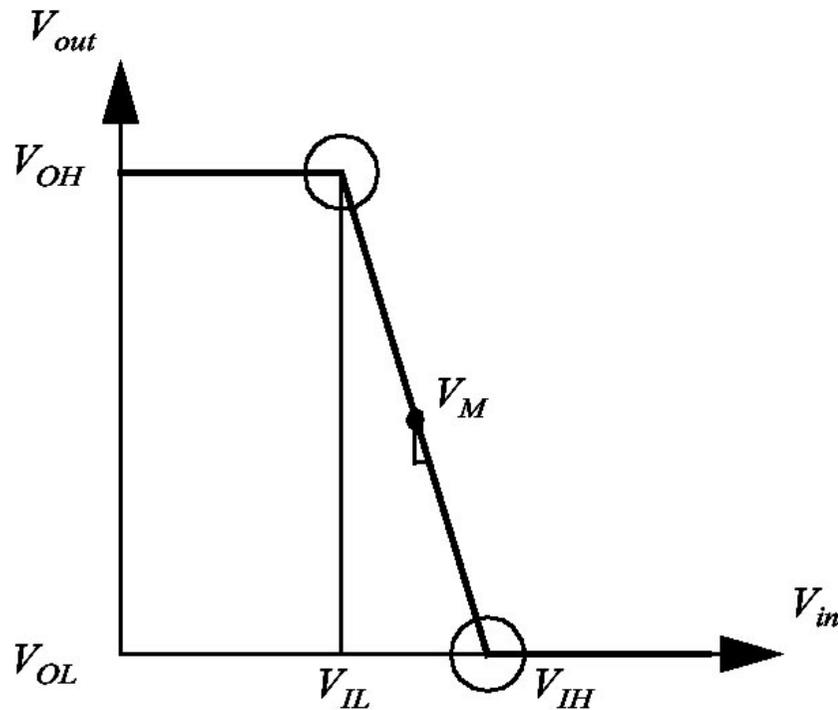
■ Study behavior of static CMOS Gates with **noisy signals**

# Noise Margins



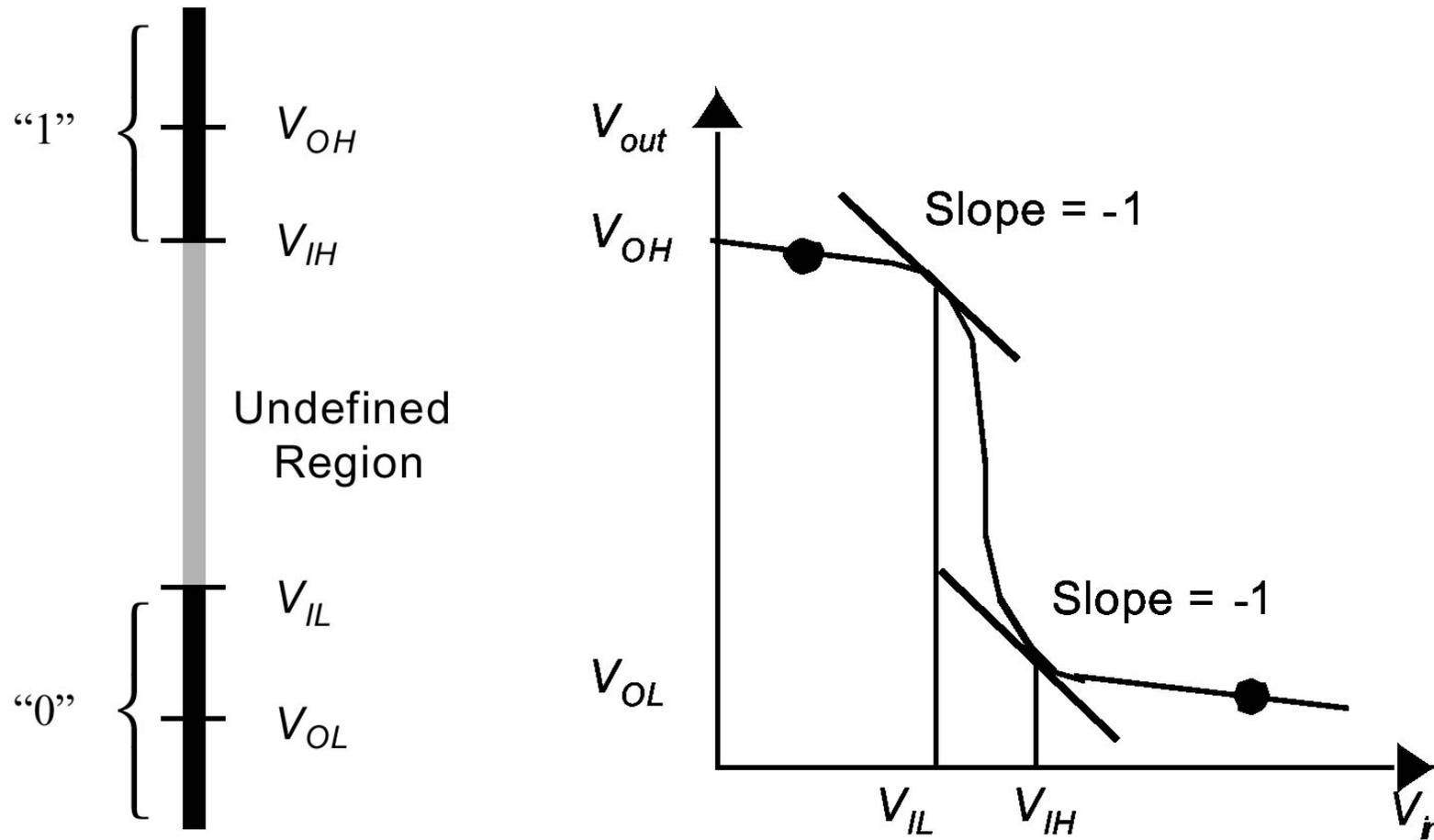
- $V_{OL}$  = Output Low Voltage
- $V_{IL}$  = Input Low Voltage
- $V_{OH}, V_{IH} = \dots$

# Noise Margins



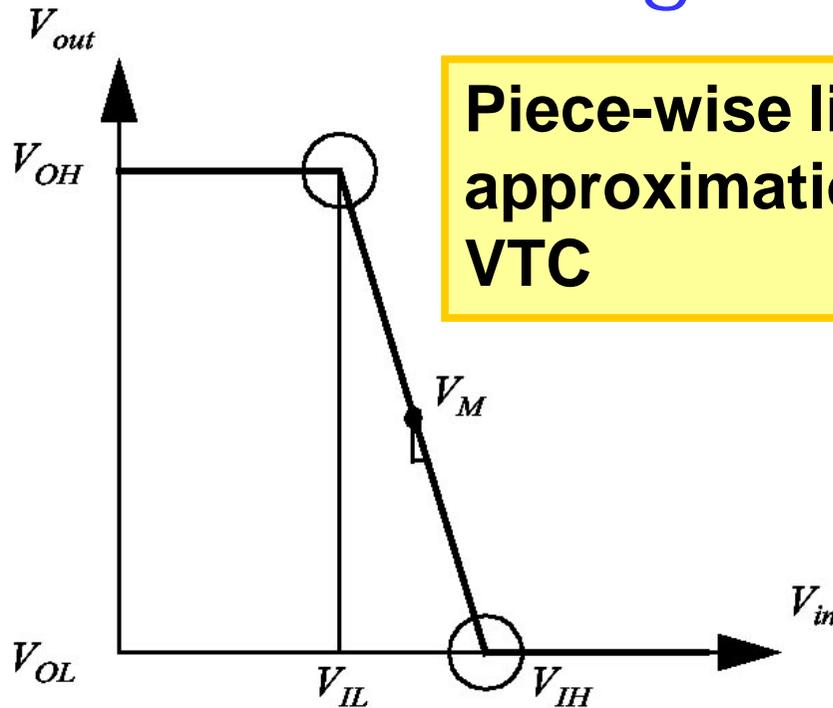
- $NM_H = V_{OH} - V_{IH} = \text{High Noise Margin}$
- $NM_L = V_{IL} - V_{OL} = \text{Low Noise Margin}$

# Noise Margin for Realistic Gates



**Exercise:** explain significance of slope = -1 for noise margin

# Noise Margin Calculation



Piece-wise linear approximation of VTC

$g$  = gain factor (slope of VTC)

We know how to compute  $V_M$   
**Next:** how to compute  $g$

$$V_{IH} - V_{IL} = -\frac{(V_{OH} - V_{OL})}{g} = -\frac{V_{DD}}{g}$$

$$V_{IH} = V_M - \frac{V_M}{g}$$

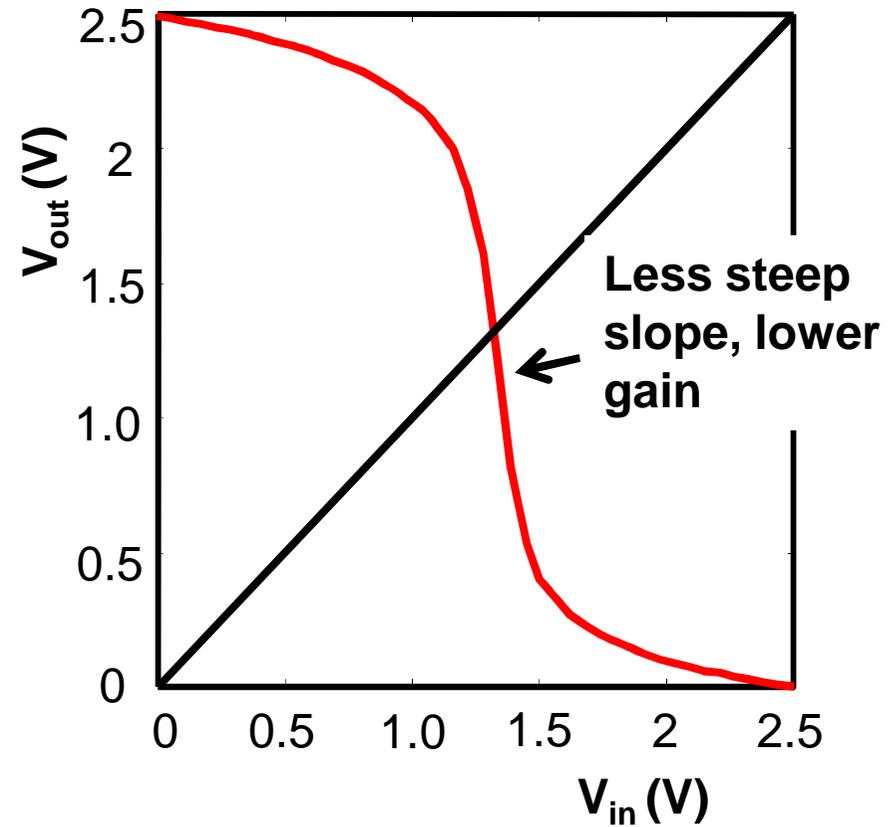
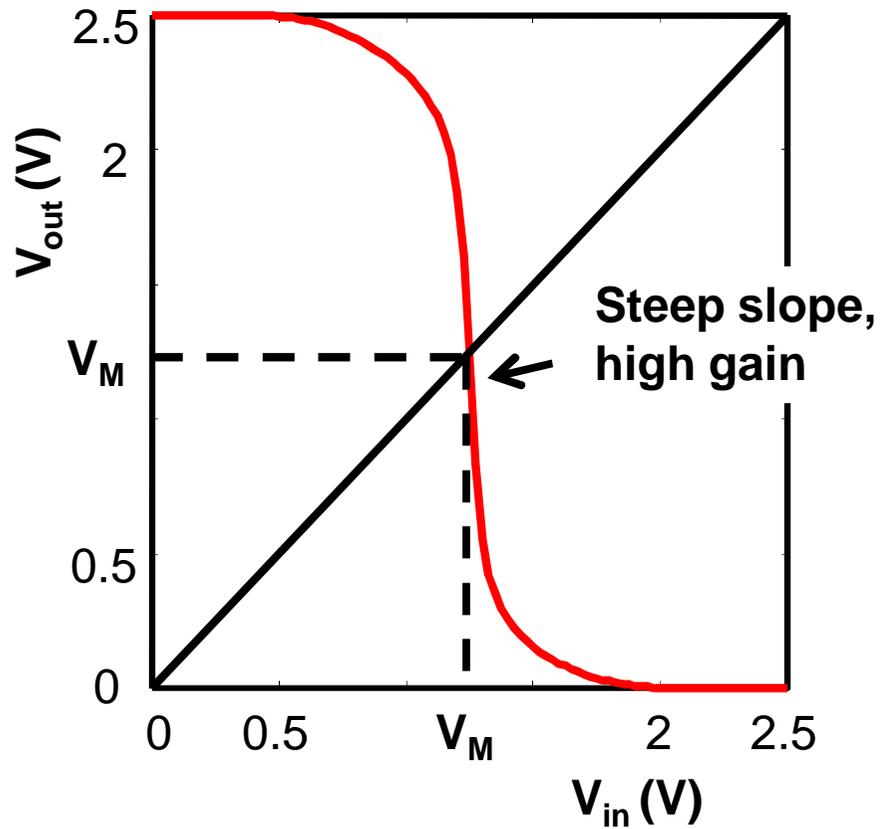
$$V_{IL} = V_M + \frac{V_{DD} - V_M}{g}$$

$$NM_H = V_{DD} - V_{IH}$$

$$NM_L = V_{IL}$$



# Different Gain

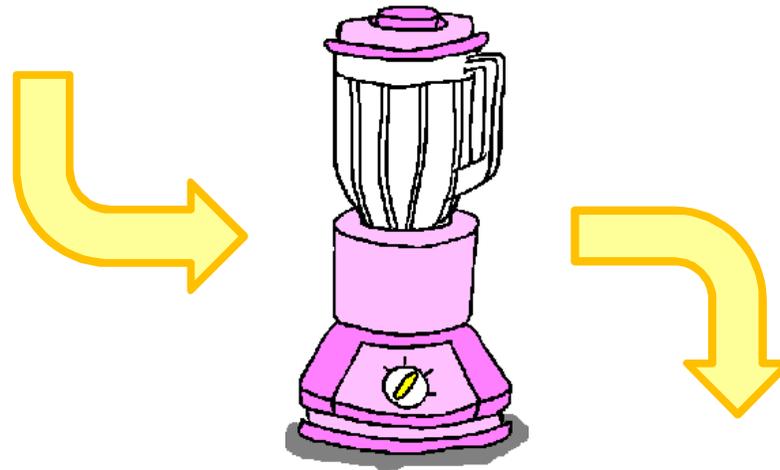


## Noise Margin Calculation (2)

- Approximate  $g$  as the slope in  $V_{out}$  vs.  $V_{in}$  at  $V_{in} = V_M$

$$k_n V_{DSATn} (V_{in} - V_{Tn} - V_{DSATn} / 2)(1 + \lambda_n V_{out}) +$$

$$k_p V_{DSATp} (V_{in} - V_{DD} - V_{Tp} - V_{DSATp} / 2)(1 + \lambda_p V_{out} - \lambda_p V_{DD}) = 0$$



$$g = \left. \frac{dV_{out}}{dV_{in}} \right|_{V_{in}=V_M} \approx \frac{1+r}{(V_M - V_T - V_{DSATp} / 2)(\lambda_n - \lambda_p)}$$

$$r = \frac{k_p V_{DSATp}}{k_n V_{DSATn}}$$

## Noise Margin Calculation (3).

$$g = \left. \frac{dV_{out}}{dV_{in}} \right|_{V_{in}=V_M} \approx \frac{1+r}{(V_M - V_T - V_{DSATp} / 2)(\lambda_n - \lambda_p)} \quad r = \frac{k_p V_{DSATp}}{k_n V_{DSATn}}$$

- Mostly determined by technology
- See example 5.2
- **Exercise:** verify calculation
- **Exercise:** explain why we add channel length modulation to the  $I_D$  expressions (we did not do this to determine  $V_M$ )

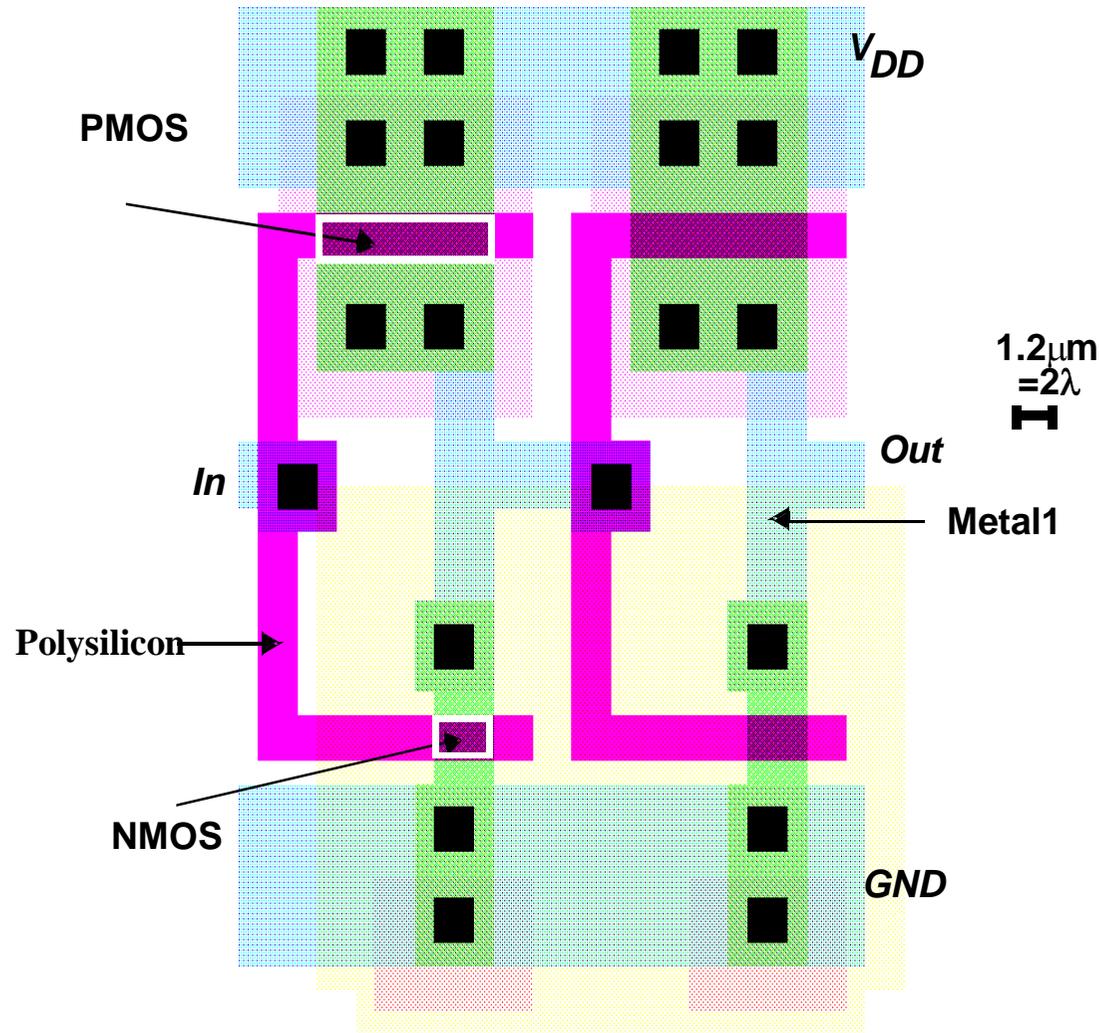
## Dynamic Behavior (Performance)

- Capacitances
- Delay

- But: we take much simpler model for capacitances compared to book.
- See the syllabus.
- § 5.4.1 of book is only illustration.

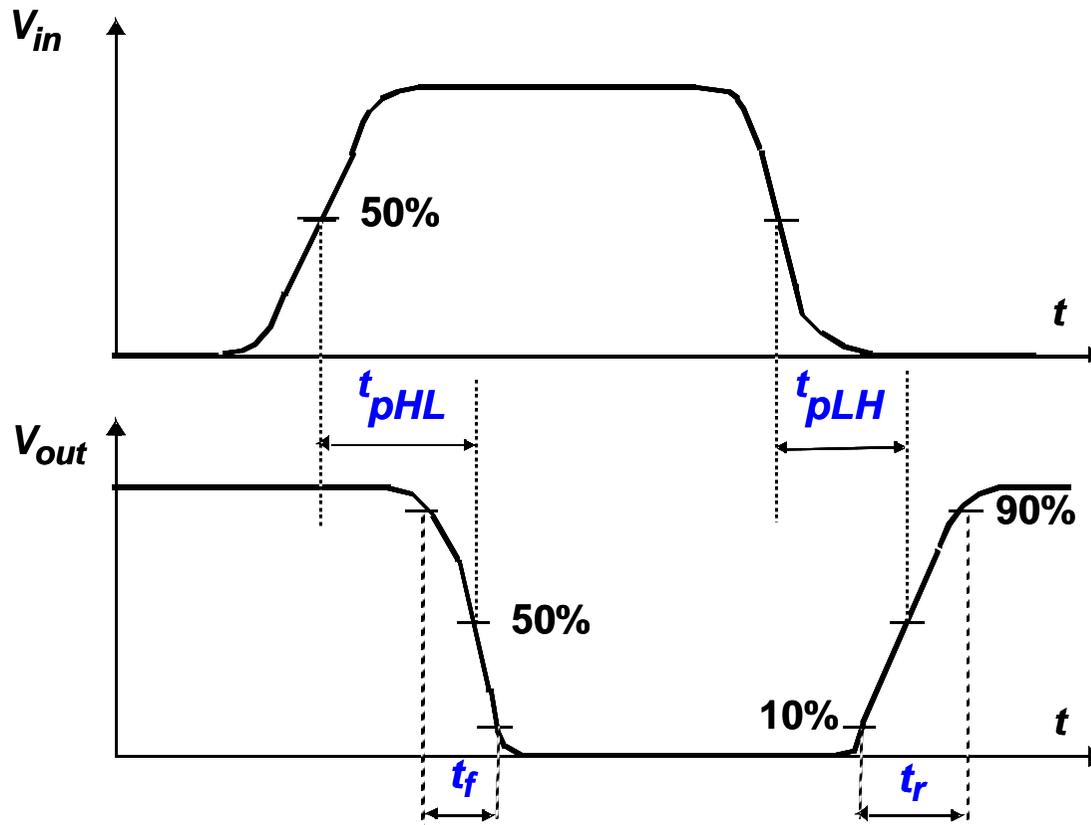


# CMOS Inverters



- What causes the delay?
- What is  $R_{on}$  ?
- Where are the capacitances?
- Which capacitances determine  $T_p$ ?

# Delay Definitions



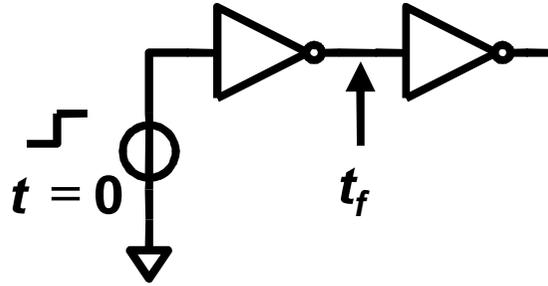
$$t_p = \frac{1}{2}(t_{pHL} + t_{pLH})$$



§ 1.3.3

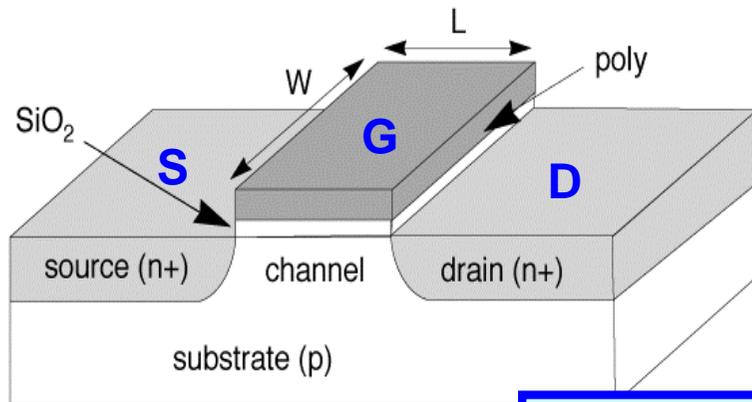
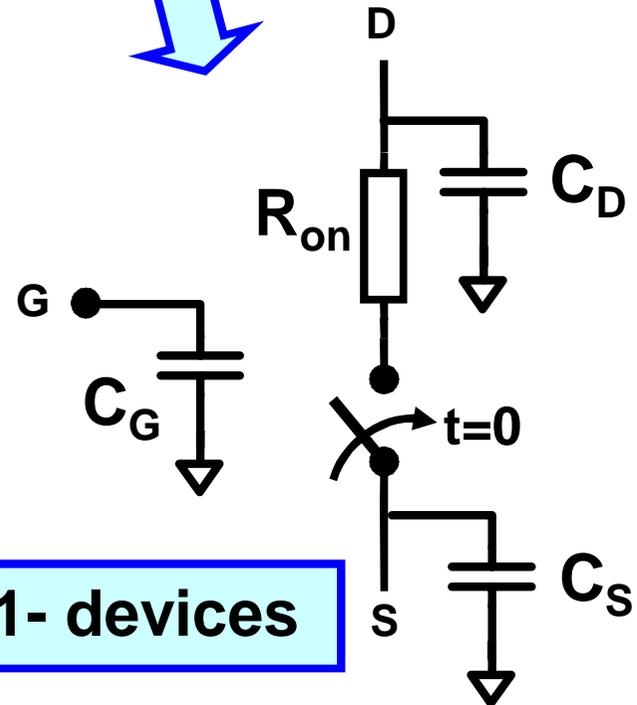
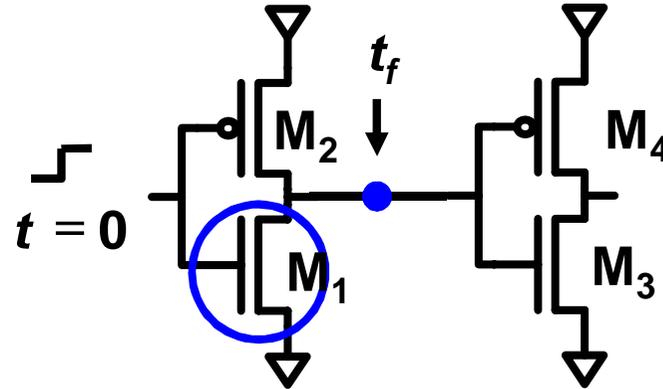
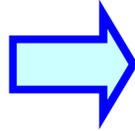
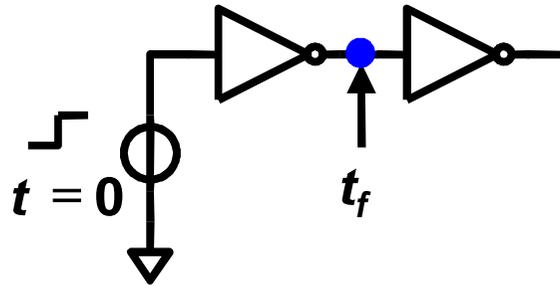
$t_p$ : property of gate  
 $t_r, t_f$ : property of signal

# CMOS Inverter Rise/Fall Delay



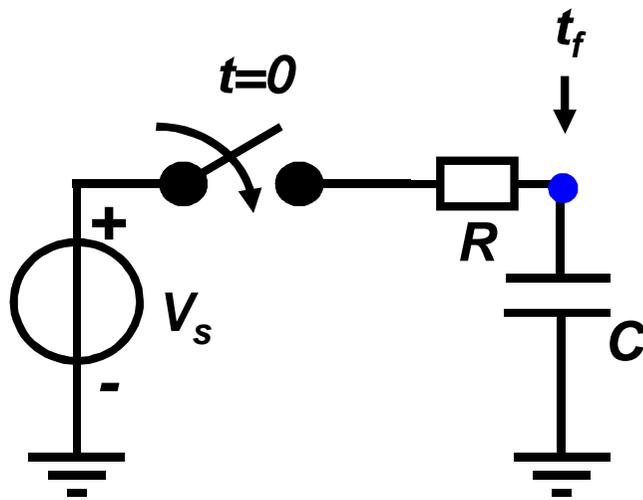
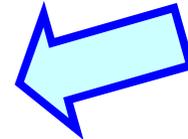
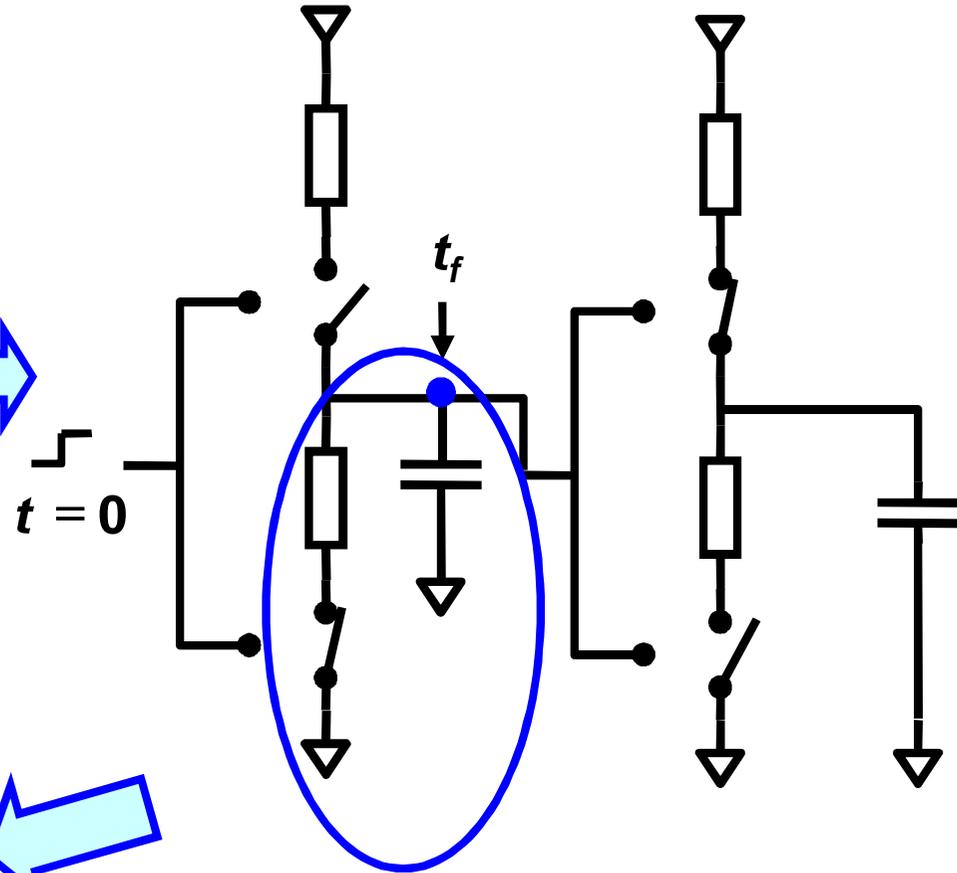
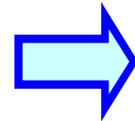
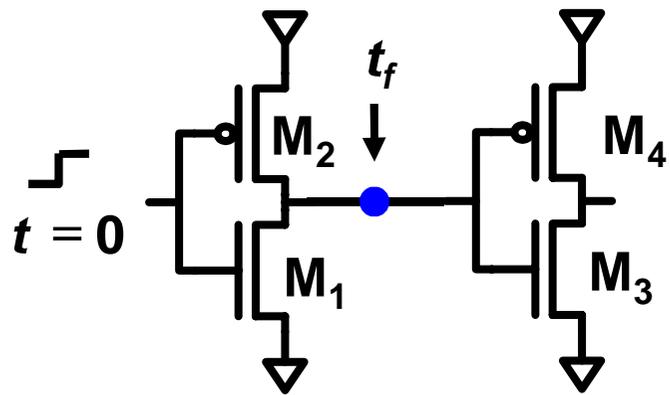
- **Goal: determine  $t_f$ ,  $t_r$  and  $t_p$**
- **First: compute relevant capacitances**
- **Second: determine equivalent  $R_{on}$**
- **Third: compute RC delay ( $\tau$ ) and scale result**
- **Assume: ideal source, step input**

# Modeling



**From module 1- devices**

# Modeling (2)



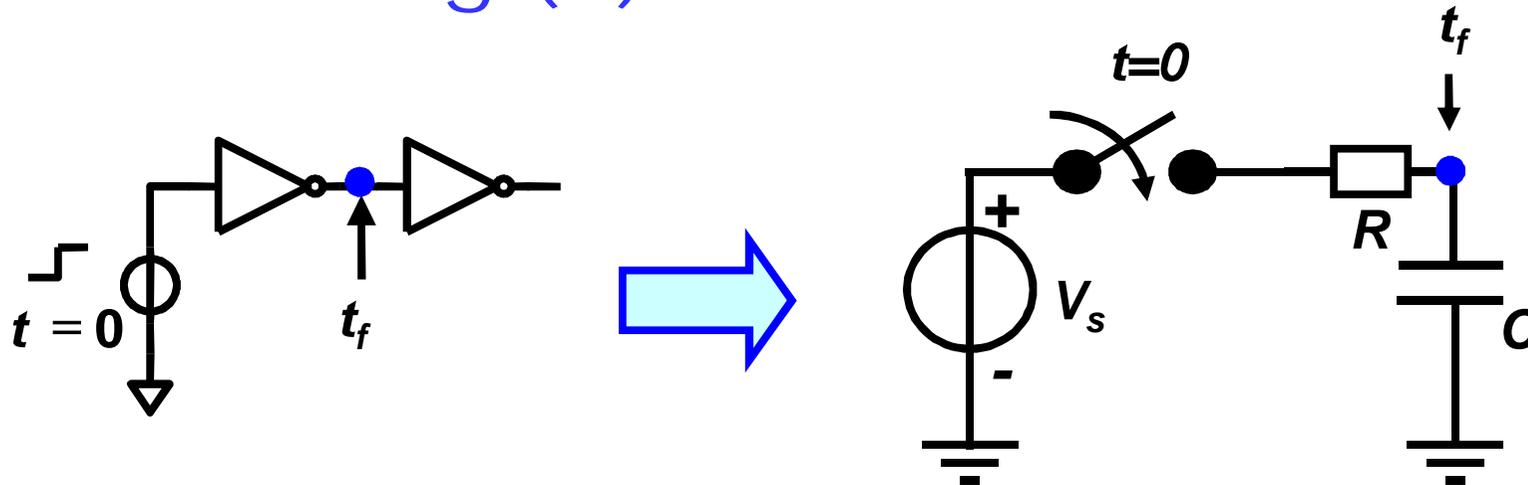
$$R = R_{on1}$$

$$C = C_{D1} + C_{D2} + C_{G3} + C_{G4}$$

$$V_s = 0$$

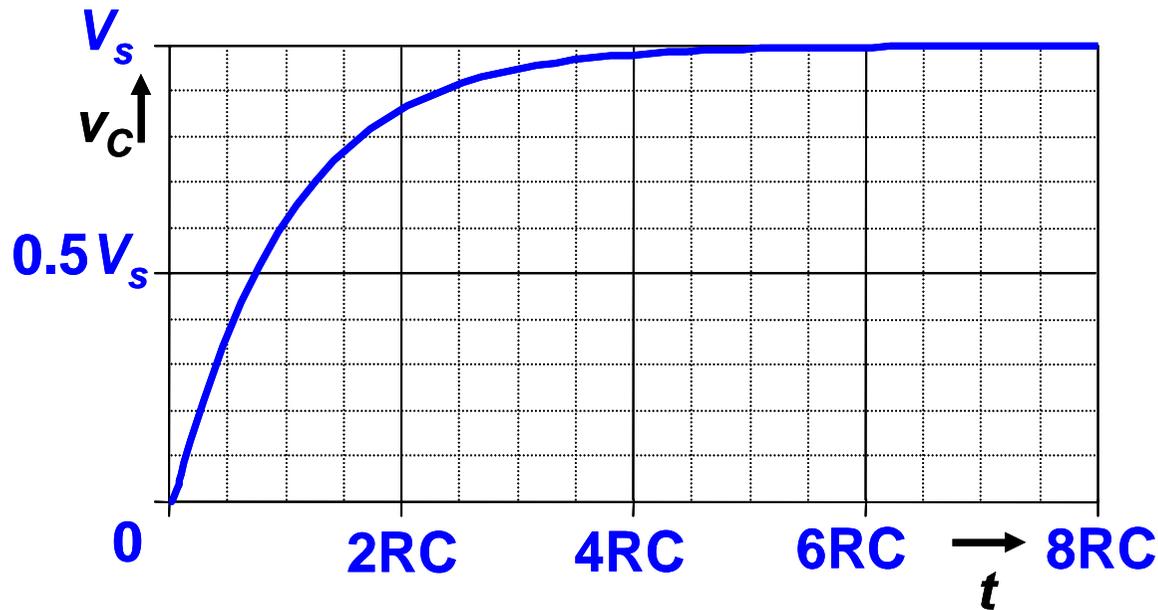
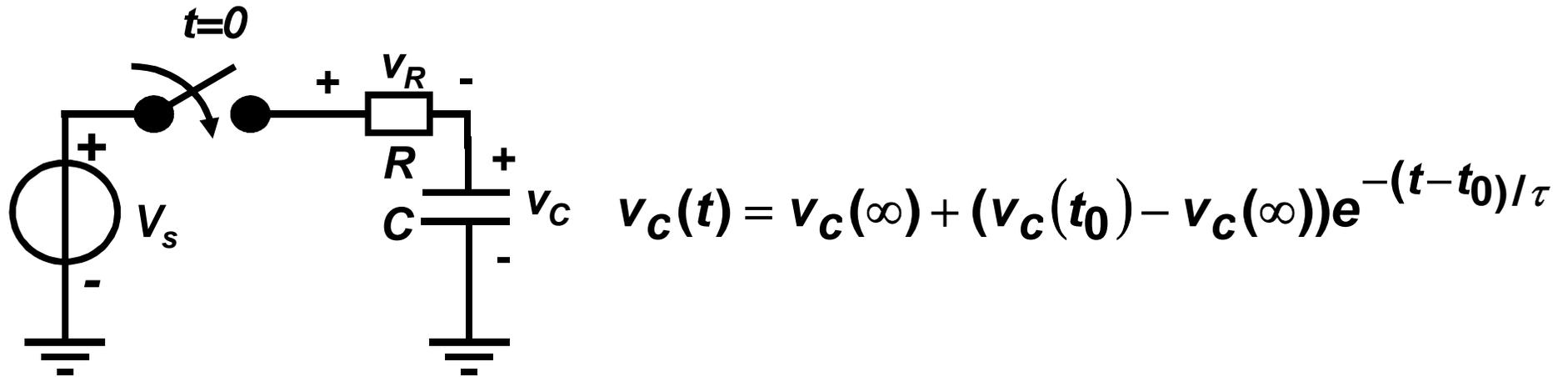
Frequently, we only include  $C_{Gi}$

## Modeling (3)



- Delay can be modeled using RC circuit
  - First order simplified model
- R is (linearized) on-resistance of active transistor
- C is sum of (linearized) C's that are switched
  - Typically,  $C_G$  of driven gate,  $C_D$  of driving gate
  - Plus relevant interconnect C
  - Might need to include interconnect R in model
- $V_s$  is final voltage of delay node (initial voltage determined by previous state)

# RC Delay Review (1)



$$RC \frac{dv_C}{dt} = V_s - v_C$$

$$v_C = V_s \left( 1 - e^{-\frac{t}{RC}} \right)$$

# RC Delay Review (2)

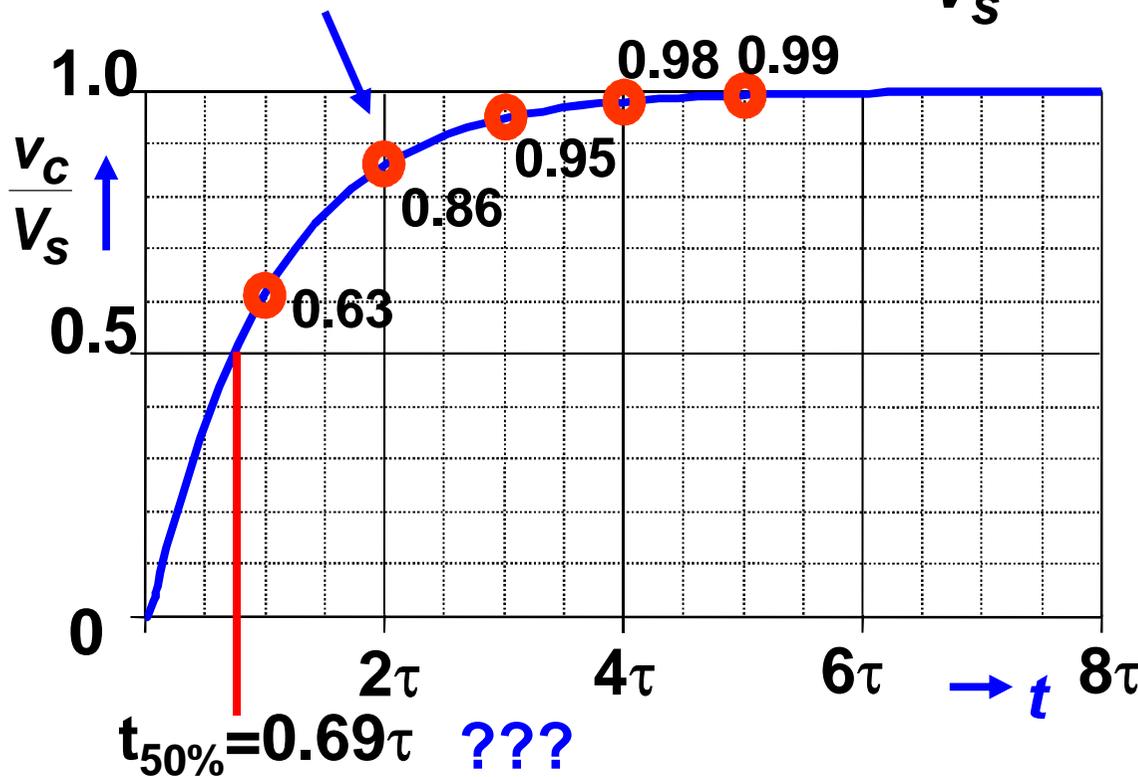
- Response can be **normalized** with respect to  $\tau=RC$  and  $V_S = v_C(t = \infty)$

$$v_C = V_S(1 - e^{-\frac{t}{RC}})$$

$$\frac{v_C}{V_S} = (1 - e^{-t/\tau})$$

Example:  $(1 - e^{-2}) = 0.86$

Each  $\tau$ -step gives **63%** of remaining swing



swing	time
0–50%	$0.69\tau$
0–63%	$1.0\tau$
10%–90%	$2.2\tau$
0–90%	$2.3\tau$

$$\frac{V_c}{V_s} = (1 - e^{-t/\tau})$$



$$0.5 = (1 - e^{-t_{50\%}/\tau})$$



$$0.5 = e^{-t_{50\%}/\tau}$$



$$2 = e^{t_{50\%}/\tau}$$

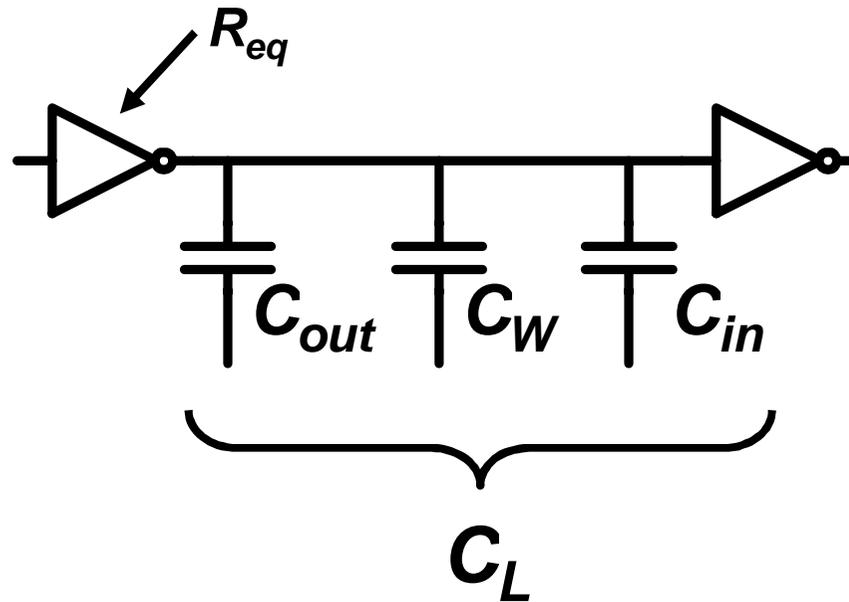


$$\ln(2) = 0.69 = t_{50\%}/\tau$$



$$t_{50\%} = 0.69\tau$$

# Inverter Propagation Delay Summary.

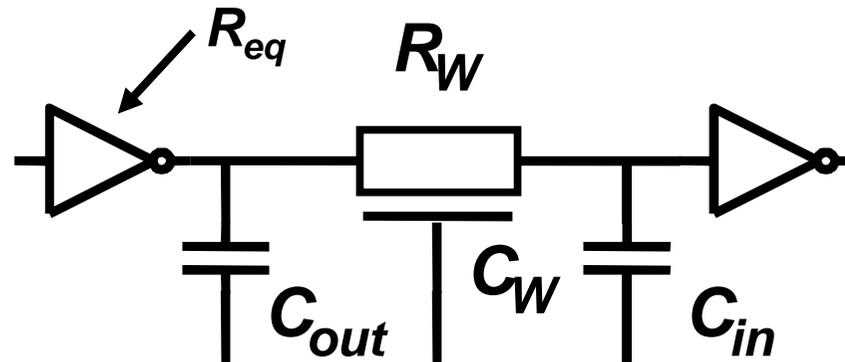


$$t_{pHL} = 0.69R_{eqn}C_L$$

$$t_{pLH} = 0.69R_{eqp}C_L$$

$$t_p = \frac{1}{2}(t_{pHL} + t_{pLH}) \quad \text{Propagation time}$$

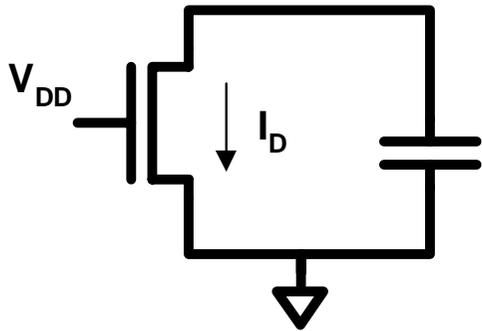
# Propagation Delay w. Wire Resistance



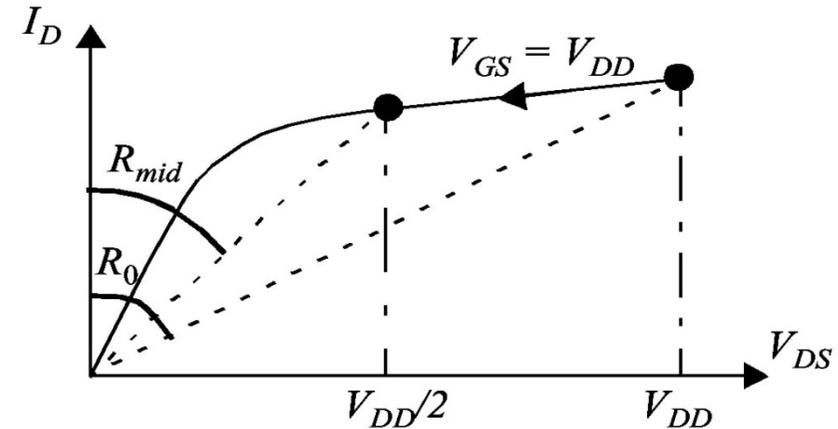
$$t_{PHL} = 0.69R_{eqn}(C_{out} + 0.5C_W) \\ + 0.69(R_{eqn} + R_W)(0.5C_W + C_{in})$$

■ See module 3, interconnect

# Equivalent $R_{on}$ ( $R_{eq}$ )



(a) Schematic



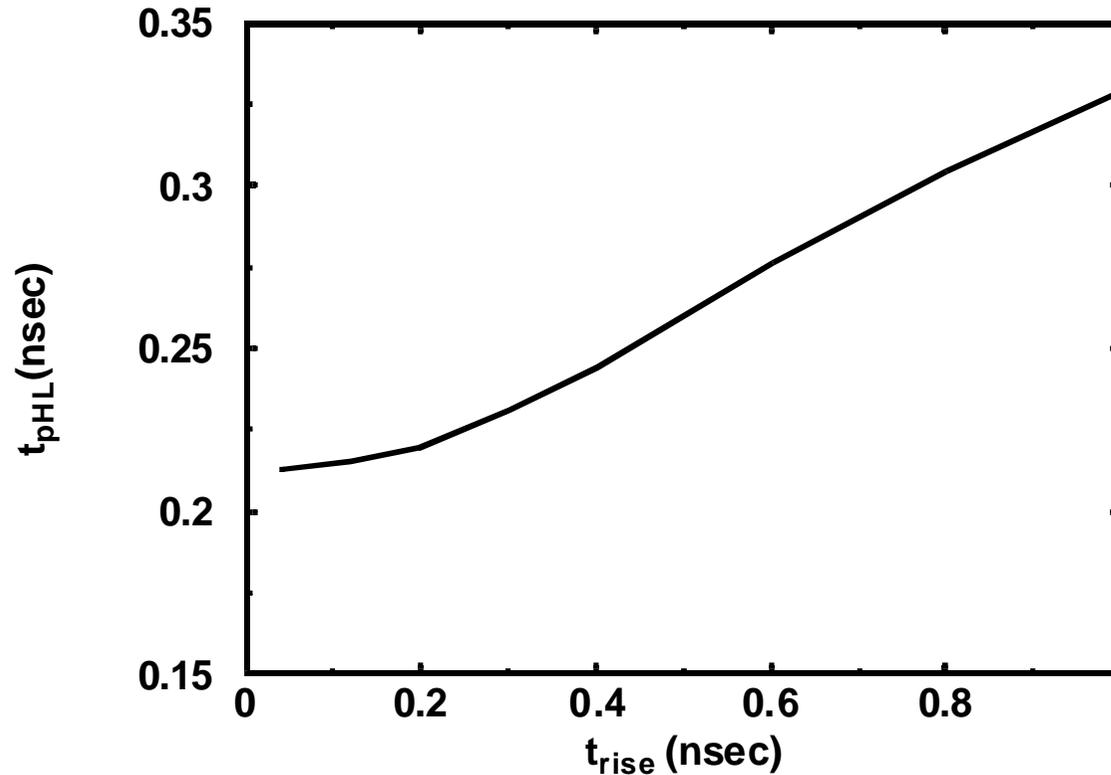
(b) trajectory traversed on ID-VDS curve.

$$R_{eq} = \frac{1}{2} \left[ \frac{V_{DD}}{I_{DSAT} (1 + \lambda V_{DD})} + \frac{V_{DD}/2}{I_{DSAT} (1 + \lambda V_{DD}/2)} \right]$$

$$\approx \frac{3}{4} \frac{V_{DD}}{I_{DSAT}} \left( 1 - \frac{5}{6} \lambda V_{DD} \right)$$

**See 3-devices, example 3.8**

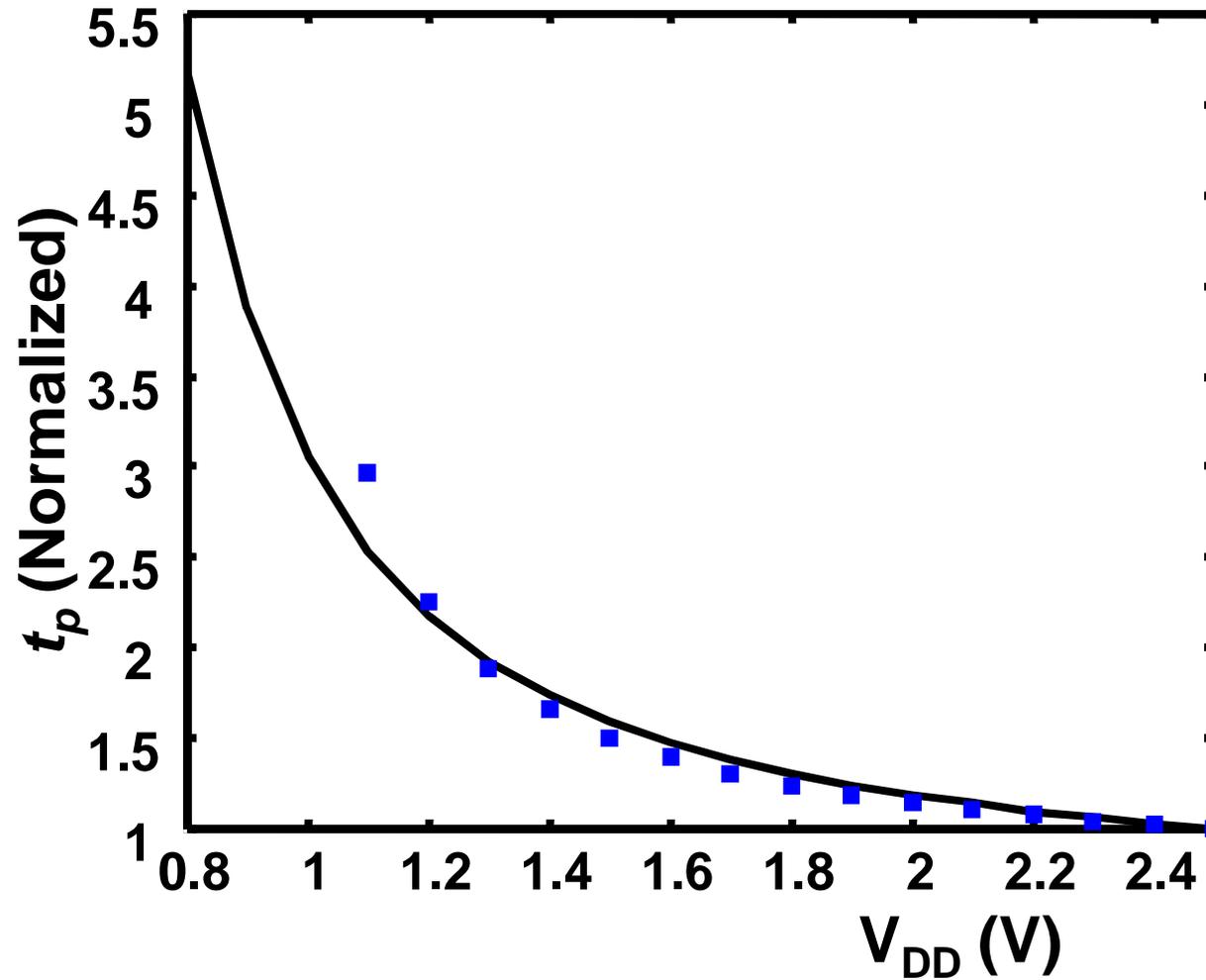
# Impact of Rise Time on Delay



$$t_{pHL} = \sqrt{t_{pHL(step)}^2 + (t_r/2)^2}$$

**Empirical from  
the first edition of  
book**

# Delay as a function of $V_{DD}$

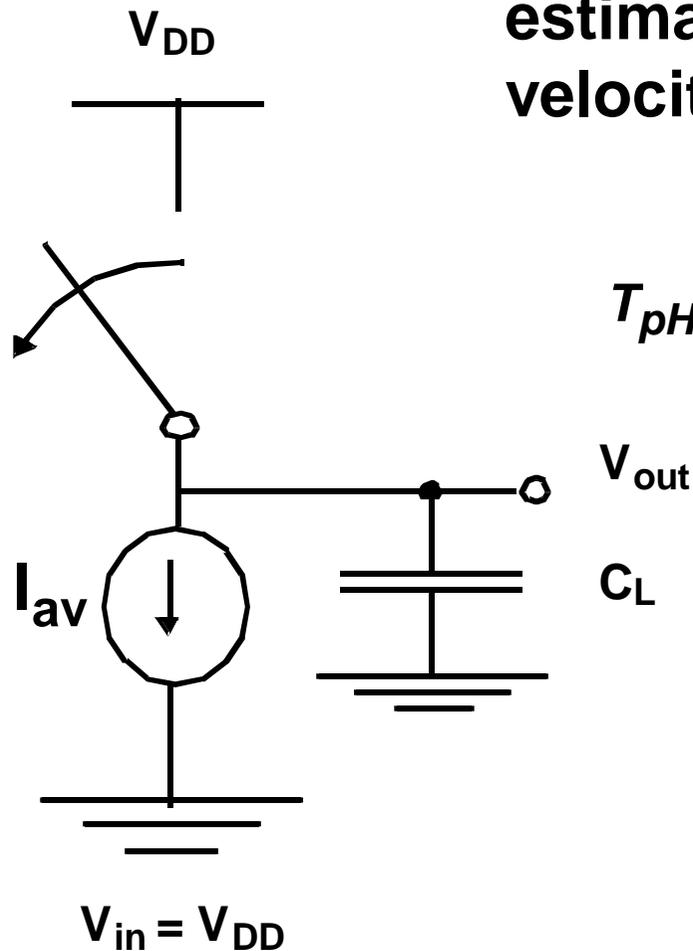


Fg.5.17

# CMOS Inverter Propagation Delay

Alternative current-based estimate for  $T_p$ , assuming velocity saturation

$$T_{pHL} = \frac{C_L \frac{V_{swing}}{2}}{I_{av}} \approx \frac{C_L V_{DD}}{2I_{DSAT}(1 + \frac{3}{4}\lambda V_{DD})}$$

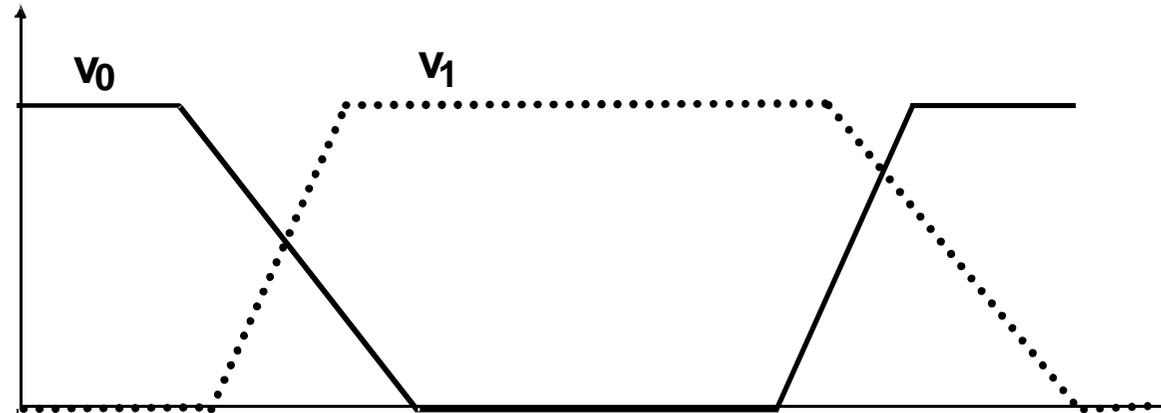
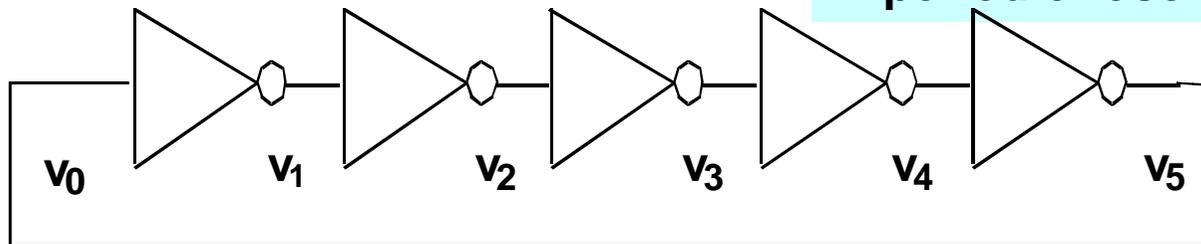


**Exercise (Problem 5.4): Derive the expression above**

# Ring Oscillator

Frequently used to obtain  $T_p$  by measurement (or simulation)

**N:** number of inverters  
 **$T_p$ :** propagation delay  
**T:** period of oscillation

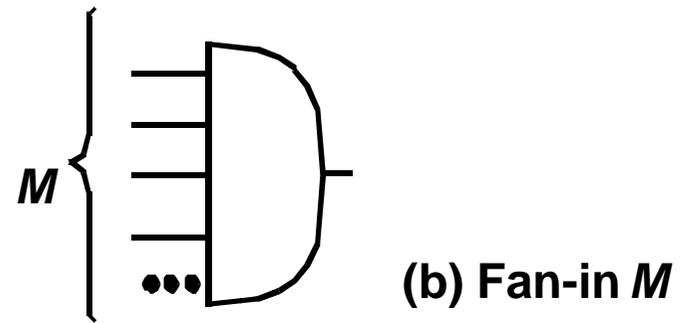
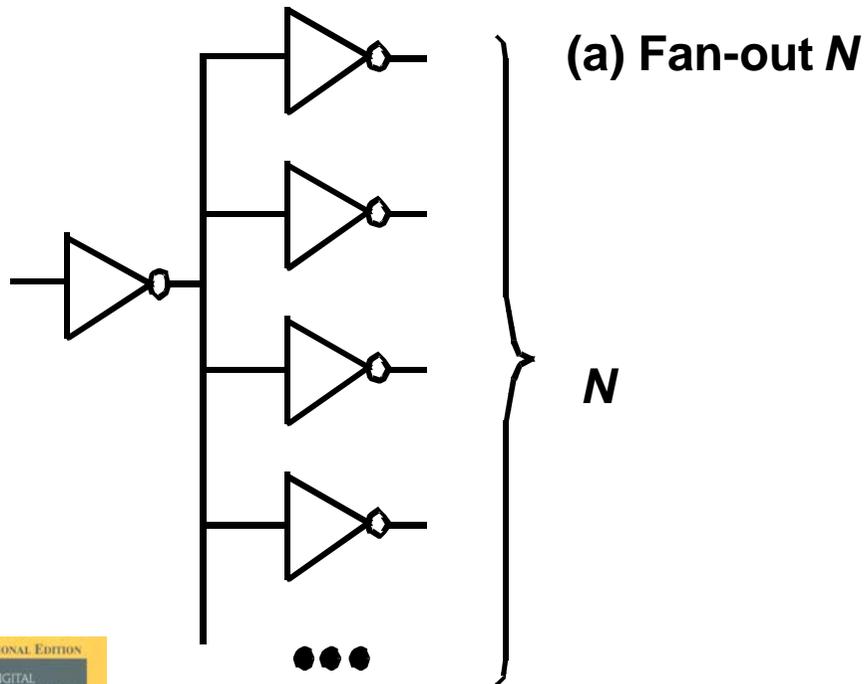


$$T = 2 \times T_p \times N \Leftrightarrow T_p = T/2N$$

**Exercise:** explain the factor 2 in the expression above



# Fan-in and Fan-out.



# Power

- Dynamic Power
- Static Power
- Metrics



[www.quitpc.com](http://www.quitpc.com)



24 hours audio  
playback time

# CMOS Power Dissipation

- Power dissipation is a **very important** circuit characteristic
- CMOS has relatively low static dissipation
- Power dissipation was the reason that CMOS technology won over bipolar and NMOS technology for digital IC's
- (Extremely) high clock frequencies increase dynamic dissipation
- Low  $V_T$  increase leakage
- Advanced IC design is a continuous struggle to contain the power requirements!



# Power Density



## Estimate

- Furnace: 2000 Watt,  $r=10\text{cm}$  →  $P \approx 6\text{Watt/cm}^2$
- Processor chip: 100 Watt,  $3\text{cm}^2$  →  $P \approx 33\text{Watt/cm}^2$

**Power-aware design**, design for low power, is blossoming subfield of VLSI Design

# Where Does Power Go in CMOS

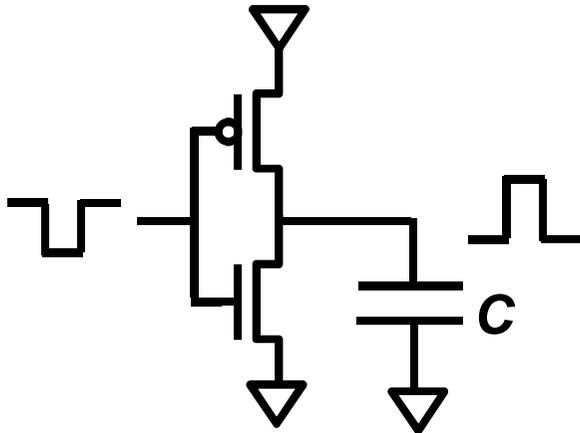
- **Dynamic Power Consumption**
  - Charging and discharging capacitors**
- **Short Circuit Currents**
  - Short circuit path between supply rails during switching**
- **Leakage**
  - Leaking diodes and transistors**
  - May be important for battery-operated equipment**

# Dynamic Power

## Dynamic Power

- $E_i$  = energy of switching event  $i$ 
  - (to first order) independent of switching speed
  - depends on process, layout
- Power = Energy/Time  
average power:  $P_{avg} = \frac{1}{T} \sum_i E_i$
- $E_i$  = Power-Delay-Product P-D
  - important quality measure
- Energy-Delay-Product E-D
  - combines power\*speed performance

# Transition Energy

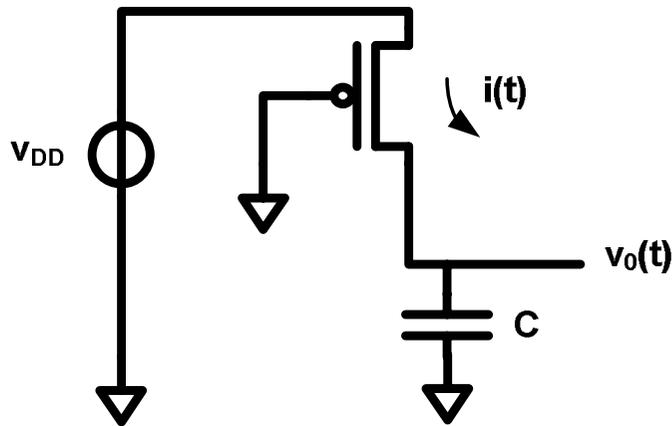


- Assume 1→0→1 transition at input
- Load cap must be charged and discharged again
- How much energy is delivered by power supply?

- Energy is power x time
- Assume timing of input signal such that output swing is complete
- Power supply only delivers energy for charging the capacitor
- Energy on capacitor is dissipated upon discharging

$$E_{delivered} = \int_0^{\infty} P(t) dt$$

# Low-to-High Transition Energy

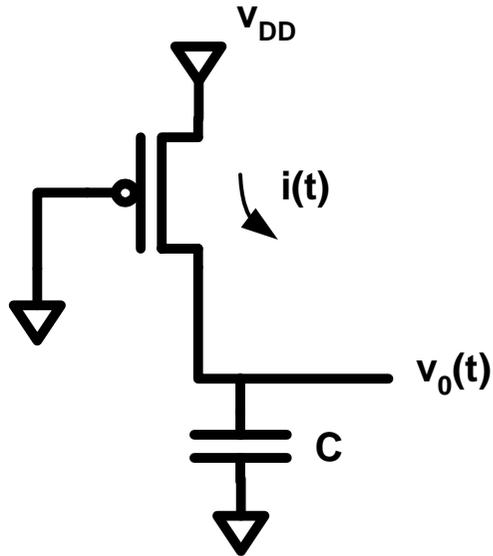


$E_{V_{DD}}$ : Energy delivered by supply

$$\begin{aligned} E_{V_{DD}} &= \int_0^{\infty} i(t) V_{DD} dt \\ &= \int_0^{\infty} C \frac{dv_o}{dt} V_{DD} dt \\ &= \int_0^{V_{DD}} C V_{DD} dv_o = [C V_{DD} v_o]_0^{V_{DD}} \\ &= C V_{DD}^2 \end{aligned}$$

- Transition energy does not depend on switching speed
- Only on load capacitance and (square of) supply voltage

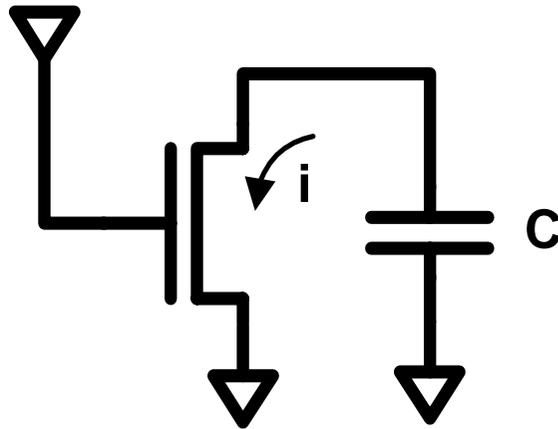
# Low-to-High Transition Energy



$E_{diss}$ : Energy dissipated in transistor

$$\begin{aligned} E_{diss} &= \int_0^{\infty} i(V_{DD} - v_0) dt \\ &= \int_0^{\infty} iV_{DD} dt - \int_0^{\infty} iv_0 dt \\ &= E_{V_{DD}} - E_C = \frac{1}{2} CV_{DD}^2 \end{aligned}$$

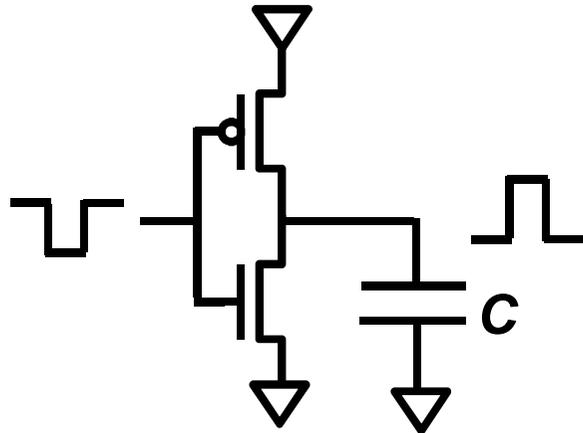
# High-to-Low Transition Energy



**Equivalent circuit**

- On high-to-low transition, supply does not deliver energy
- Any energy that is on capacitor after charging, is destroyed (converted into heat, dissipated) upon discharging
- Show that this is all the energy on C:  $\frac{1}{2}CV_{DD}^2$

# Dissipation Cycle



## In one cycle:

- Source delivers  $CV_{DD}^2$  upon charging C
- Half of that is dissipated in pull-up transistor
- Rest is stored on capacitor
- And is completely destroyed upon discharging C
- So,  $CV_{DD}^2$  is energy expended per cycle

# CMOS Dynamic Power Dissipation.

$$\mathbf{Energy = E_{charge} + E_{discharge}}$$

$$\mathbf{Power = \frac{Energy}{Time} = \frac{Energy}{transition} \times \frac{\#transitions}{time}}$$
$$\mathbf{= CV_{DD}^2 \times f}$$

- Independent of transistor on-resistances
- Can only reduce  $C$ ,  $V_{DD}$  or  $f$  to reduce power
- In this formula,  $f$  accounts for switching activity (not necessarily a simple regular waveform)
- Can also include probability of switching explicitly, take  $\alpha$  as switching factor

# Summary

- **First Glance**
- **Digital Gate Characterization (§ 1.3)**
- **Static Behavior (Robustness) (§ 5.3)**
  - **VTC**
  - **Switching Threshold**
  - **Noise Margins**
- **Dynamic Behavior (Performance) (§ 5.4)**
  - **Capacitances**
  - **Delay**
- **Power (§ 5.5)**
  - **Dynamic Power, Static Power, Metrics**